

L & S BAND GaAs FET [Plastic Mold Lead-less PKG]**DESCRIPTION**

The MGF0951P GaAs FET with an N-channel schottky Gate, is designed for use L/S band amplifiers.

FEATURES

- High output power
Po=31dBm(TYP.) @f=2.15GHz, Pin=20dBm
- High power gain
Glp=13dB(TYP.) @f=2.15GHz
- High power added efficiency
 η_{add} =50%(TYP.) @f=2.15GHz, Pin=20dBm
- Plastic Mold Lead-less PKG

APPLICATION

- For L/S Band power amplifiers

QUALITY

- GG

RECOMMENDED BIAS CONDITIONS

- Vds=10V • Ids=200mA • Rg=500 Ω

Delivery Tape & Reel(1.5K)

Absolute maximum ratings (Ta=25°C)

Symbol	Parameter	Ratings	Unit
VGSO	Gate to source breakdown voltage	-15	V
VGDO	Gate to drain breakdown voltage	-15	V
ID	Drain current	800	mA
IGR	Reverse gate current	-2.5	mA
IGF	Forward gate current	5.4	mA
PT	Total power dissipation	6.0	W
Tch	Channel temperature	150	°C
Tstg	Storage temperature	-40 to +150	°C

Recommended maximum ratings (Ta=25°C)

Symbol	Parameter	Ratings	Unit
Tch	Channel temperature	150	°C

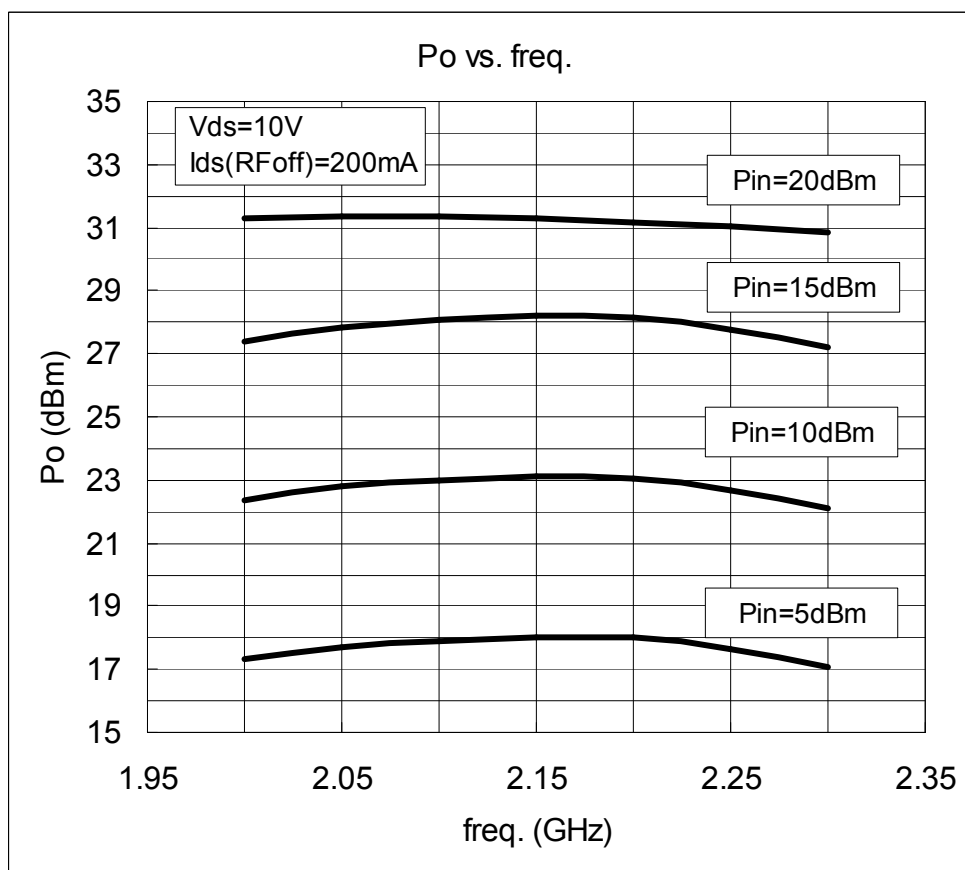
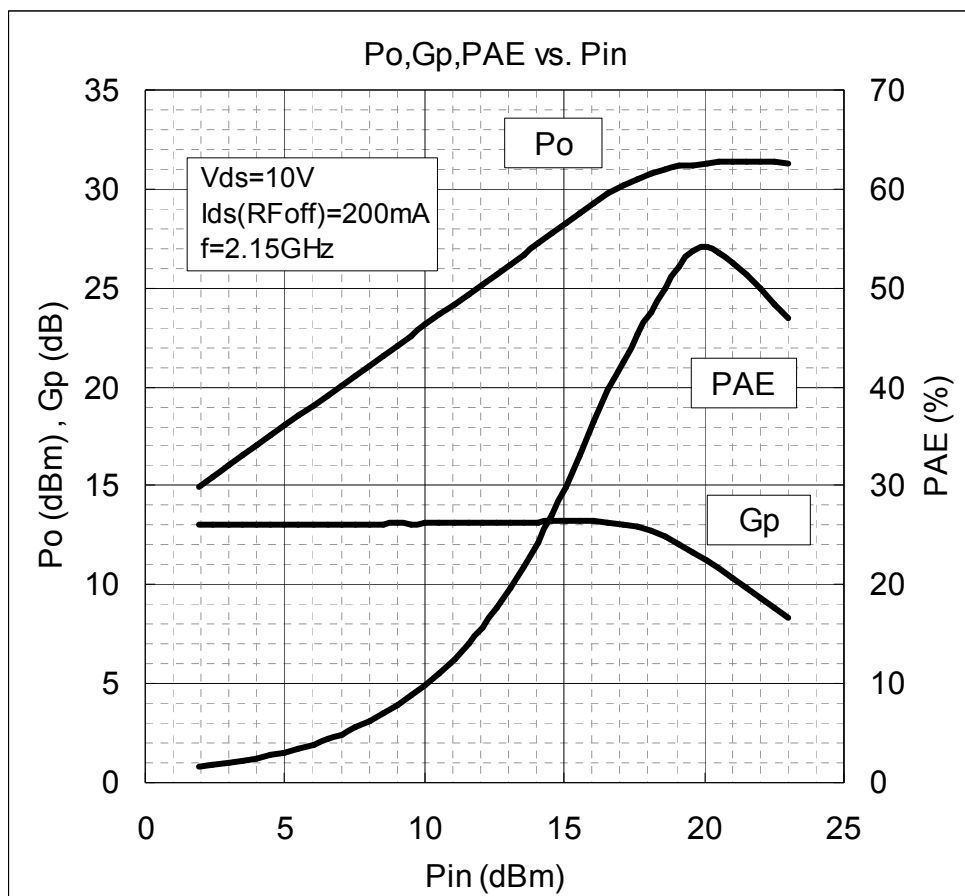
Electrical characteristics (Ta=25°C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
VGS(off)	Gate to source cut-off voltage	VDS=3V, ID=2.5mA	-1	-3	-5	V
gm	Transconductance	VDS=3V, ID=300mA	--	200	--	mS
Po	Output power	VDS=10V, ID=200mA, f=2.15GHz	29.5	31	--	dBm
η_{add} *1	Power added Efficiency	*1: Pin=20dBm, *2: Pin=10dBm	--	50	--	%
GLP *2	Linear Power Gain	*3: f1=2.15GHz, f2=2.16GHz	11	13	--	dB
IM3 *3	3 rd order Modulation Distortion	Po(SCL)=20dBm	--	-45	--	dBc
Rth(ch-c)	Thermal Resistance *1	ΔV_f Method	--	20	25	°C/W

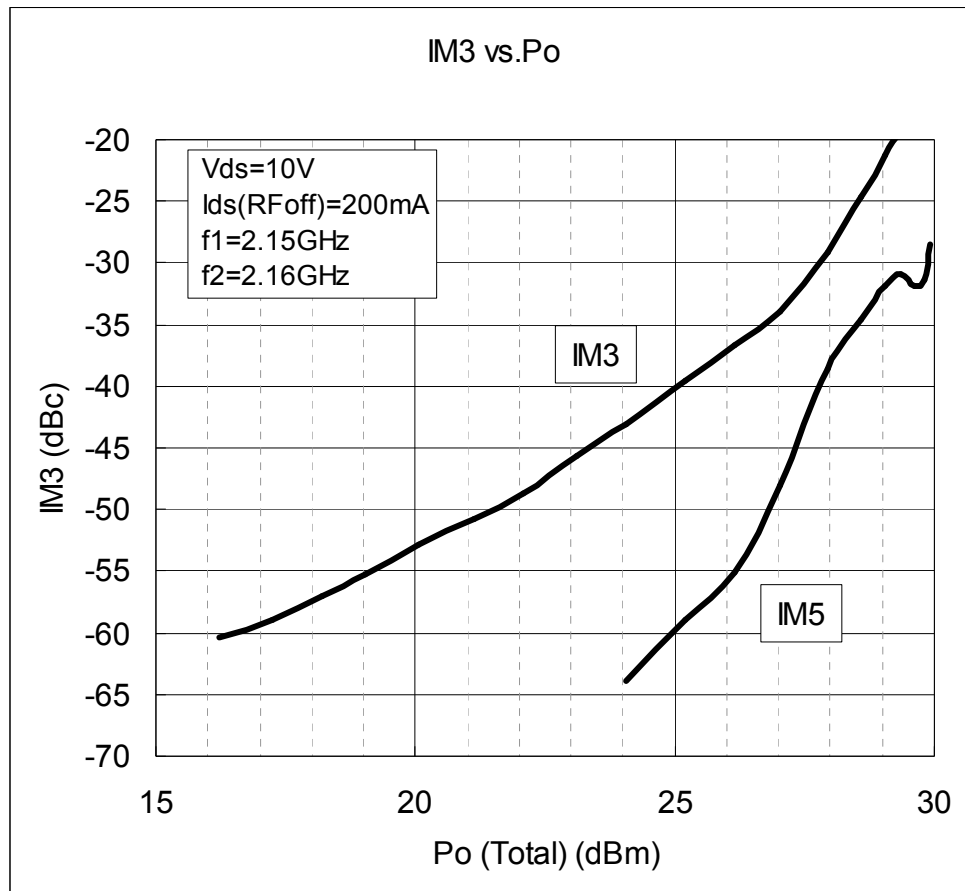
*1: Channel to case / Above parameters, ratings, limits are subject to change.

Fig.1

MGF0951P TYPICAL CHARACTERISTICS



MGF0951P TYPICAL CHARACTERISTICS



MGF0951P S PARAMETERS (Ta=25°C,VD=10V,ID=200mA)

f (MHz)	S Parameter(TYP.)								K	MSG/MAG (dB)
	S11		S21		S12		S22			
	Magn.	Angle(deg.)	Magn.	Angle(deg.)	Magn.	Angle(deg.)	Magn.	Angle(deg.)		
600	0.847	-98.9	7.176	117.6	0.039	44.1	0.186	-115.6	0.476	22.7
800	0.827	-115.4	5.972	106.5	0.043	37.8	0.207	-126.0	0.564	21.4
1000	0.807	-127.9	5.076	97.3	0.046	34.1	0.225	-133.2	0.666	20.4
1200	0.797	-137.6	4.392	89.6	0.048	31.5	0.240	-137.7	0.767	19.6
1400	0.785	-145.0	3.867	82.8	0.051	29.6	0.256	-140.5	0.855	18.8
1600	0.777	-151.3	3.450	76.6	0.052	29.0	0.270	-142.7	0.951	18.2
1800	0.772	-156.1	3.127	71.0	0.053	28.2	0.284	-143.5	1.027	16.7
2000	0.763	-160.3	2.865	65.7	0.056	28.0	0.295	-144.3	1.099	15.2
2200	0.754	-164.1	2.655	60.8	0.058	27.2	0.303	-144.8	1.173	14.1
2400	0.745	-167.7	2.485	55.8	0.060	27.4	0.314	-145.3	1.223	13.3
2600	0.733	-171.3	2.342	50.9	0.064	26.7	0.325	-145.4	1.269	12.5
2800	0.720	-175.0	2.223	46.1	0.067	25.9	0.335	-145.3	1.312	11.9
3000	0.709	-178.8	2.114	41.4	0.070	25.4	0.342	-145.4	1.358	11.3
3200	0.698	177.4	2.023	36.7	0.073	24.8	0.346	-146.1	1.399	10.7
3400	0.689	173.5	1.939	31.8	0.076	23.9	0.350	-147.5	1.426	10.2
3600	0.678	169.7	1.867	27.2	0.080	22.8	0.351	-148.9	1.451	9.7
3800	0.669	166.0	1.807	22.6	0.084	22.0	0.351	-149.5	1.462	9.3
4000	0.660	162.4	1.756	18.1	0.089	21.6	0.346	-150.5	1.458	8.9
4200	0.651	158.4	1.715	13.4	0.095	20.2	0.340	-152.0	1.451	8.6
4400	0.641	154.1	1.677	8.5	0.101	18.6	0.334	-154.4	1.442	8.3
4600	0.630	149.4	1.640	3.6	0.108	16.8	0.332	-156.5	1.413	8.0
4800	0.619	144.6	1.604	-1.2	0.114	15.0	0.328	-158.4	1.410	7.7
5000	0.608	140.0	1.572	-6.1	0.122	12.9	0.323	-160.6	1.398	7.4
5200	0.599	135.2	1.543	-11.1	0.129	10.5	0.318	-163.5	1.378	7.1
5400	0.589	130.4	1.512	-16.2	0.137	7.9	0.316	-167.3	1.356	6.9
5600	0.577	125.2	1.486	-21.3	0.146	5.1	0.316	-170.5	1.337	6.6
5800	0.563	120.3	1.466	-26.4	0.156	2.2	0.314	-172.9	1.305	6.4
6000	0.549	115.0	1.453	-31.6	0.165	-0.9	0.307	-175.5	1.287	6.2
6200	0.533	108.4	1.440	-37.1	0.177	-4.6	0.300	-178.9	1.263	6.0
6400	0.518	101.4	1.427	-42.9	0.189	-8.3	0.293	177.0	1.243	5.8
6600	0.505	93.1	1.417	-48.9	0.201	-12.7	0.286	173.4	1.222	5.6
6800	0.497	84.1	1.403	-55.3	0.213	-17.2	0.269	169.2	1.206	5.4
7000	0.501	74.8	1.386	-61.9	0.226	-22.5	0.245	162.5	1.185	5.3

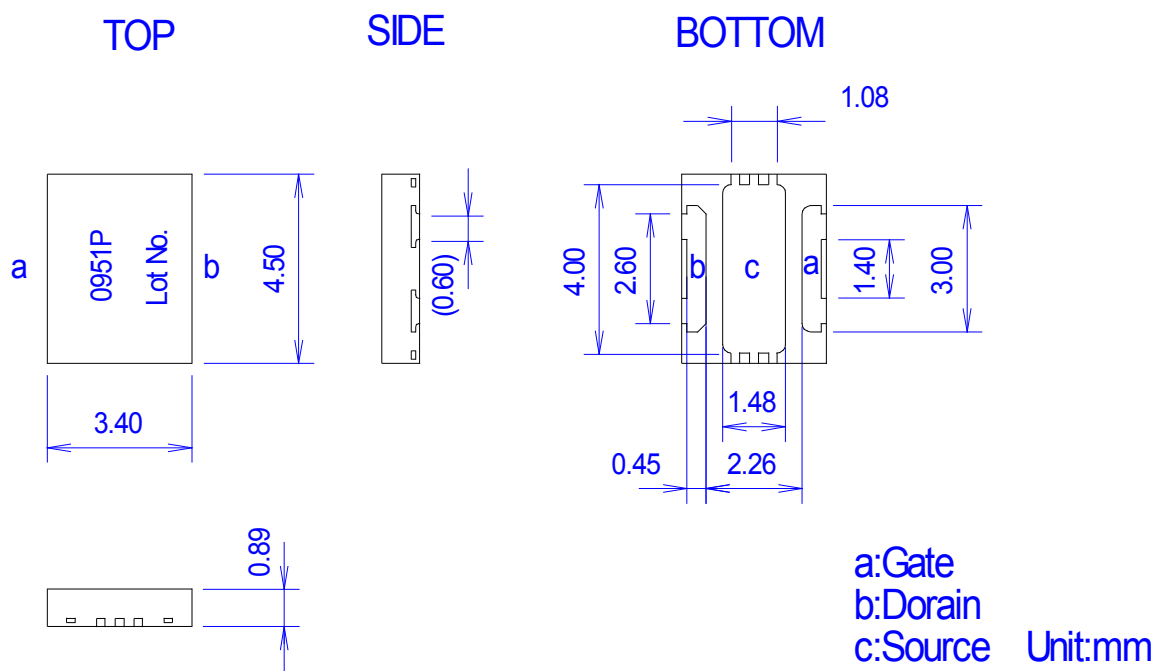
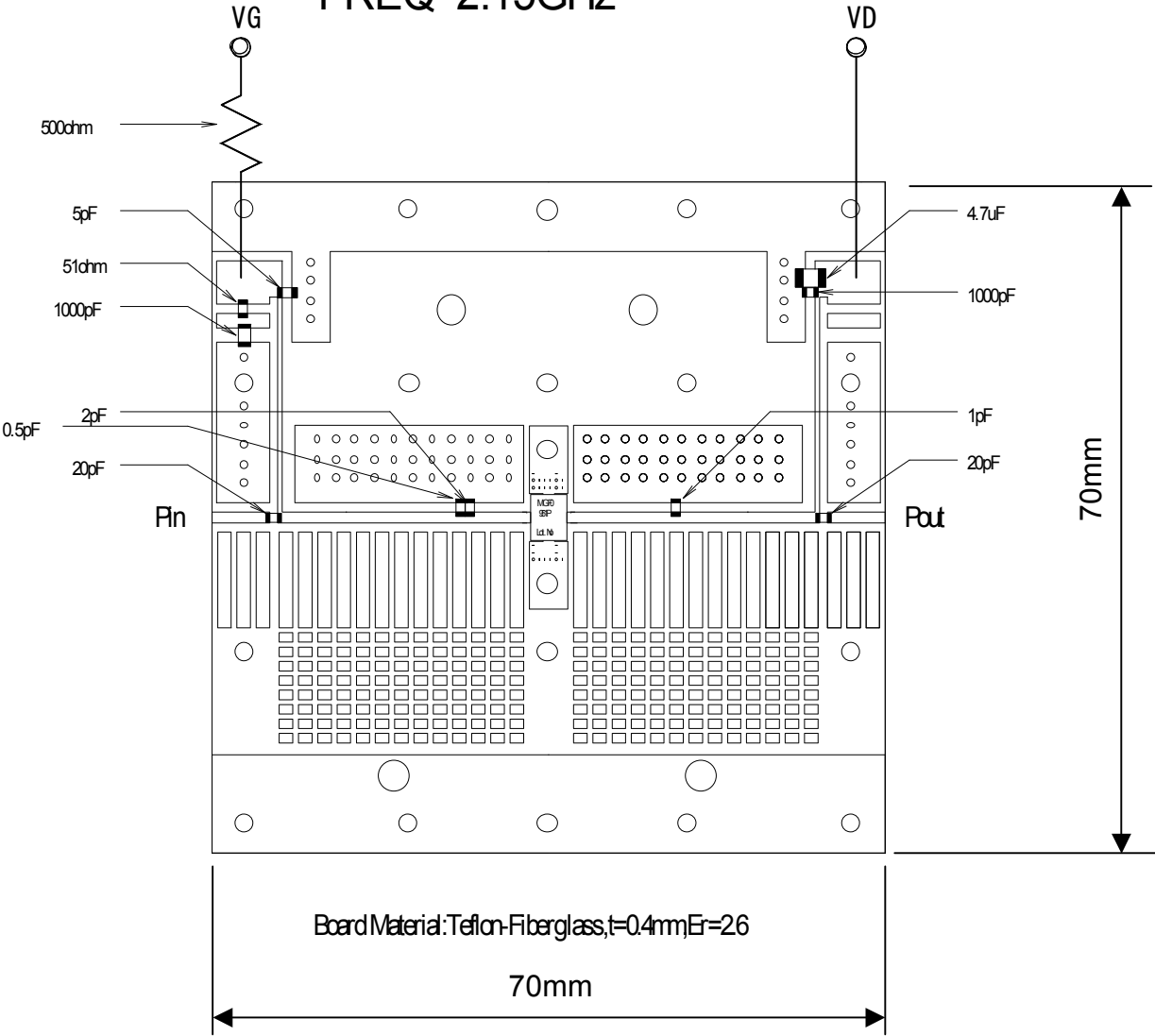
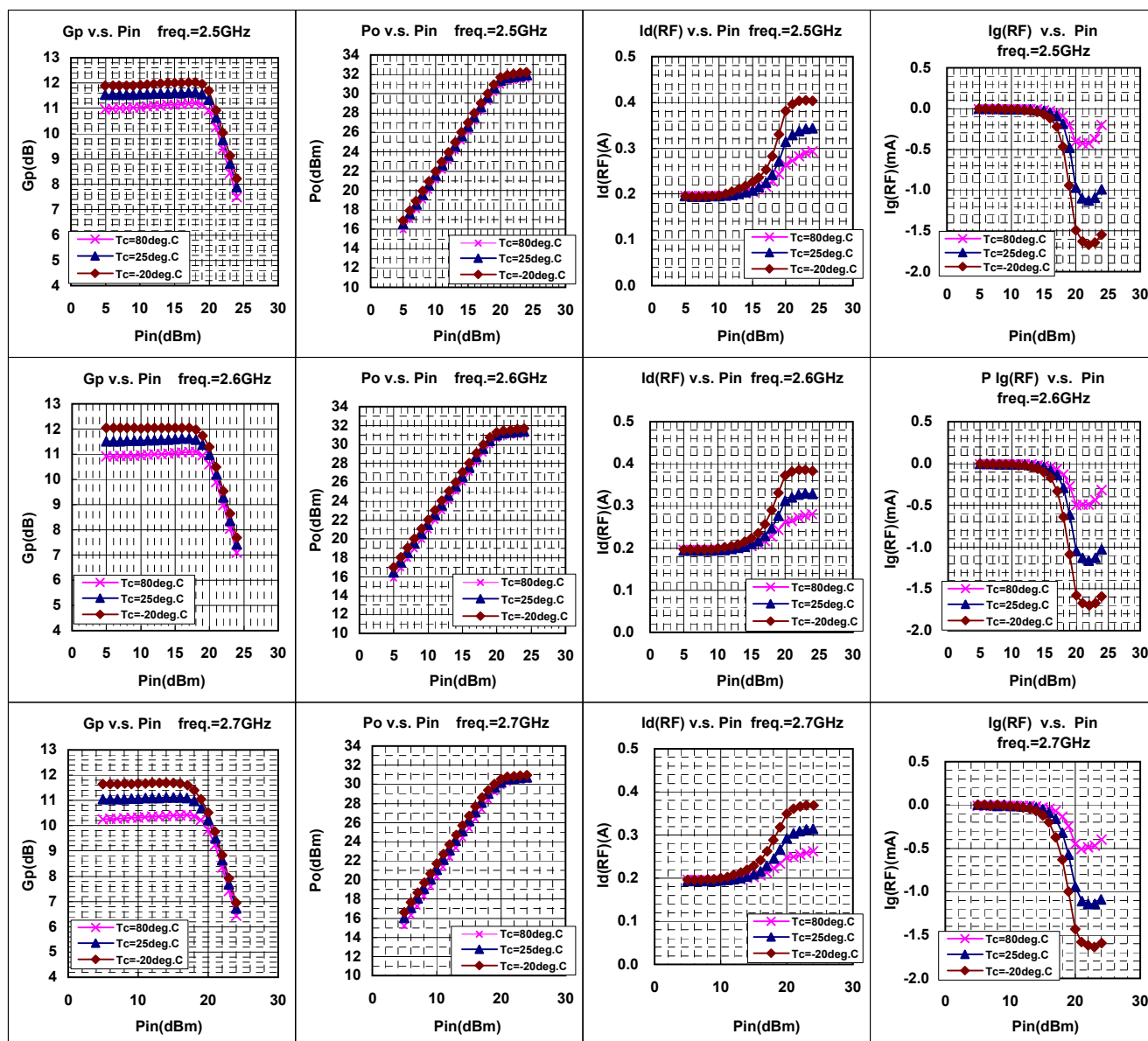


Fig1.OUTLINE DRAWING

MGF0951P TESTFIXTURE FREQ=2.15GHz

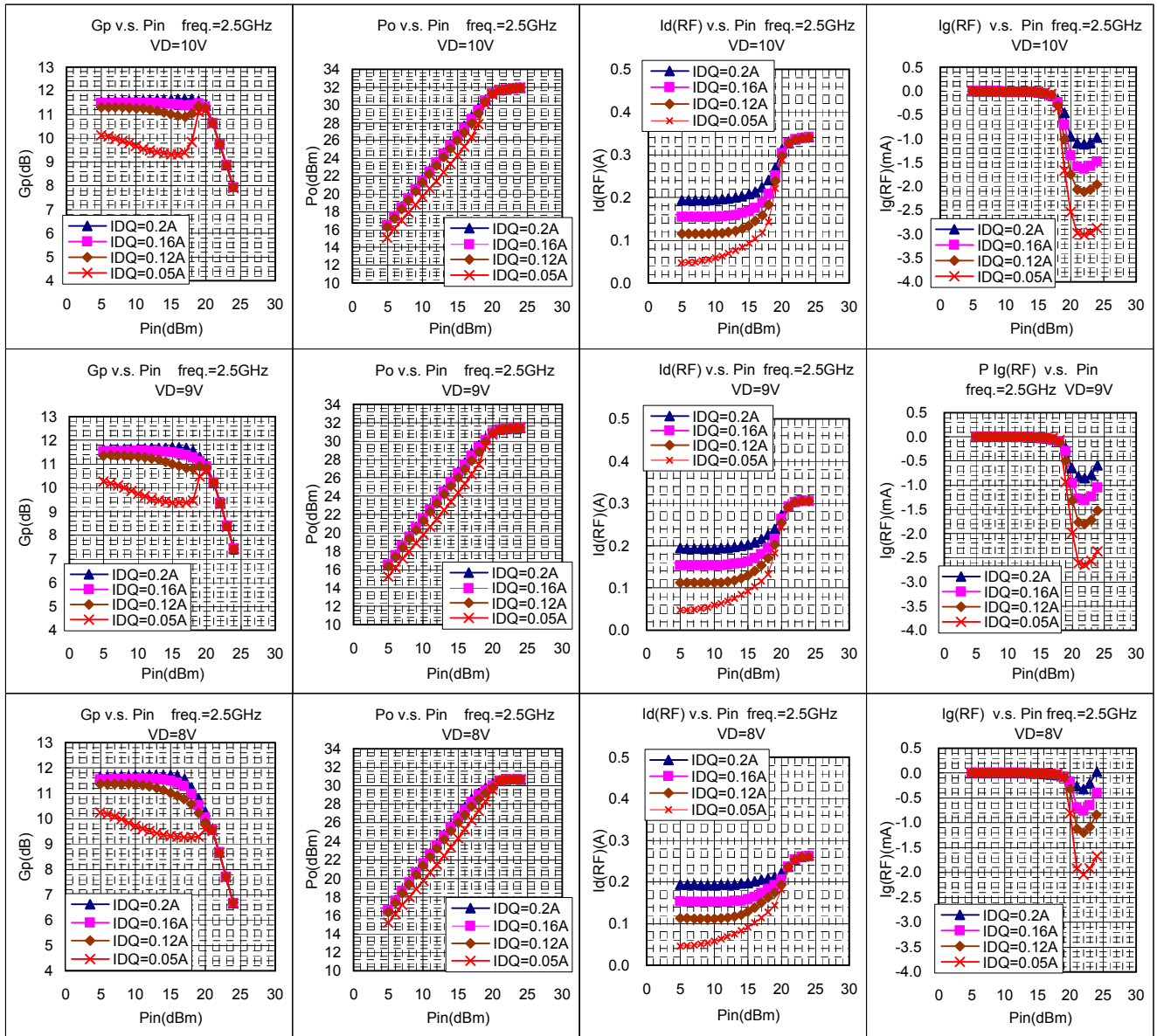


MGF0951P RF TEST DATA(CW) VD=10V,Idq=0.2A
Gp,Po,Id(RF),Ig(RF) v.s. Pin



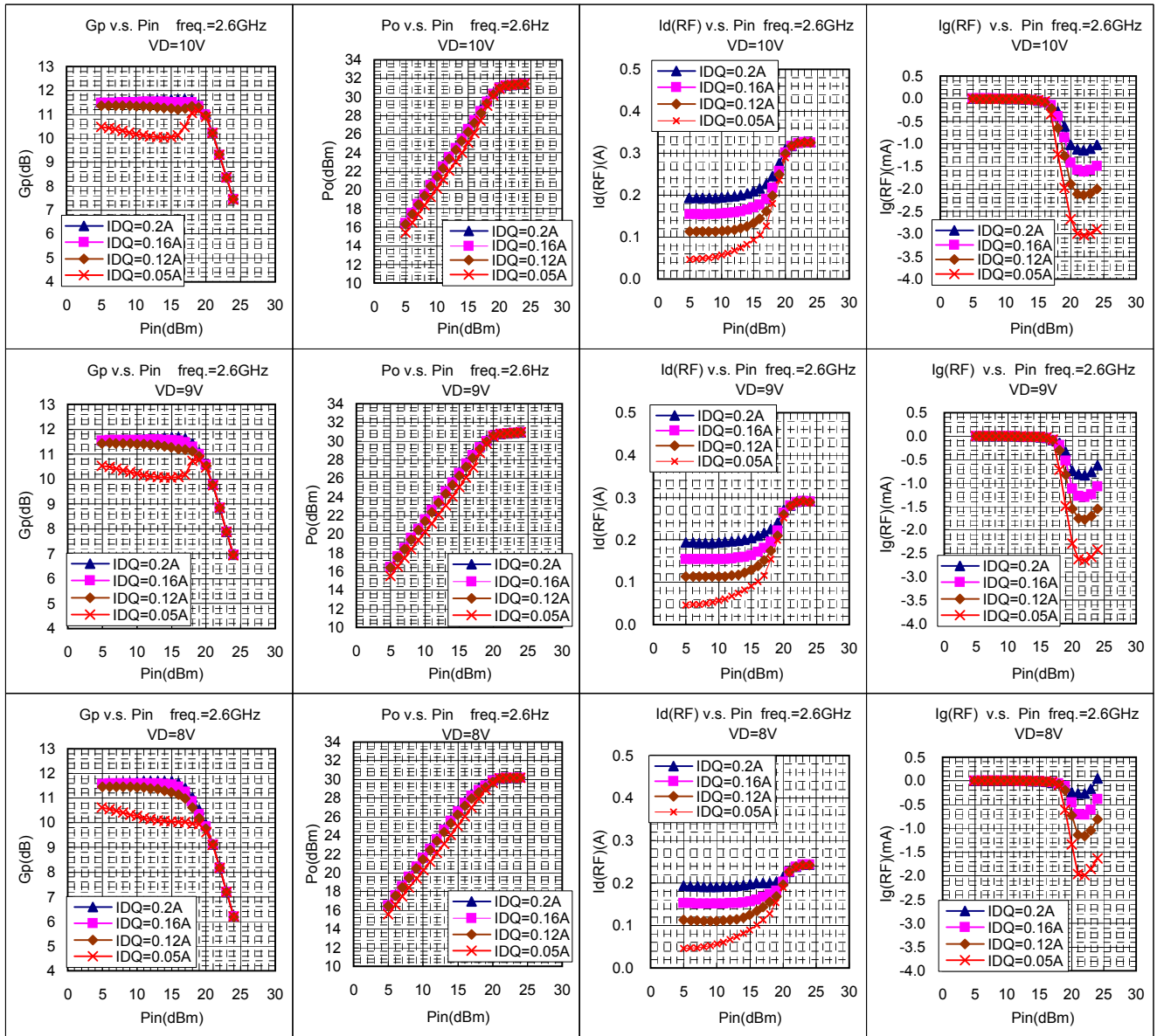
MGF0951P RF TEST DATA(CW)

Gp,Po,Id(RF),Ig(RF) v.s. Pin



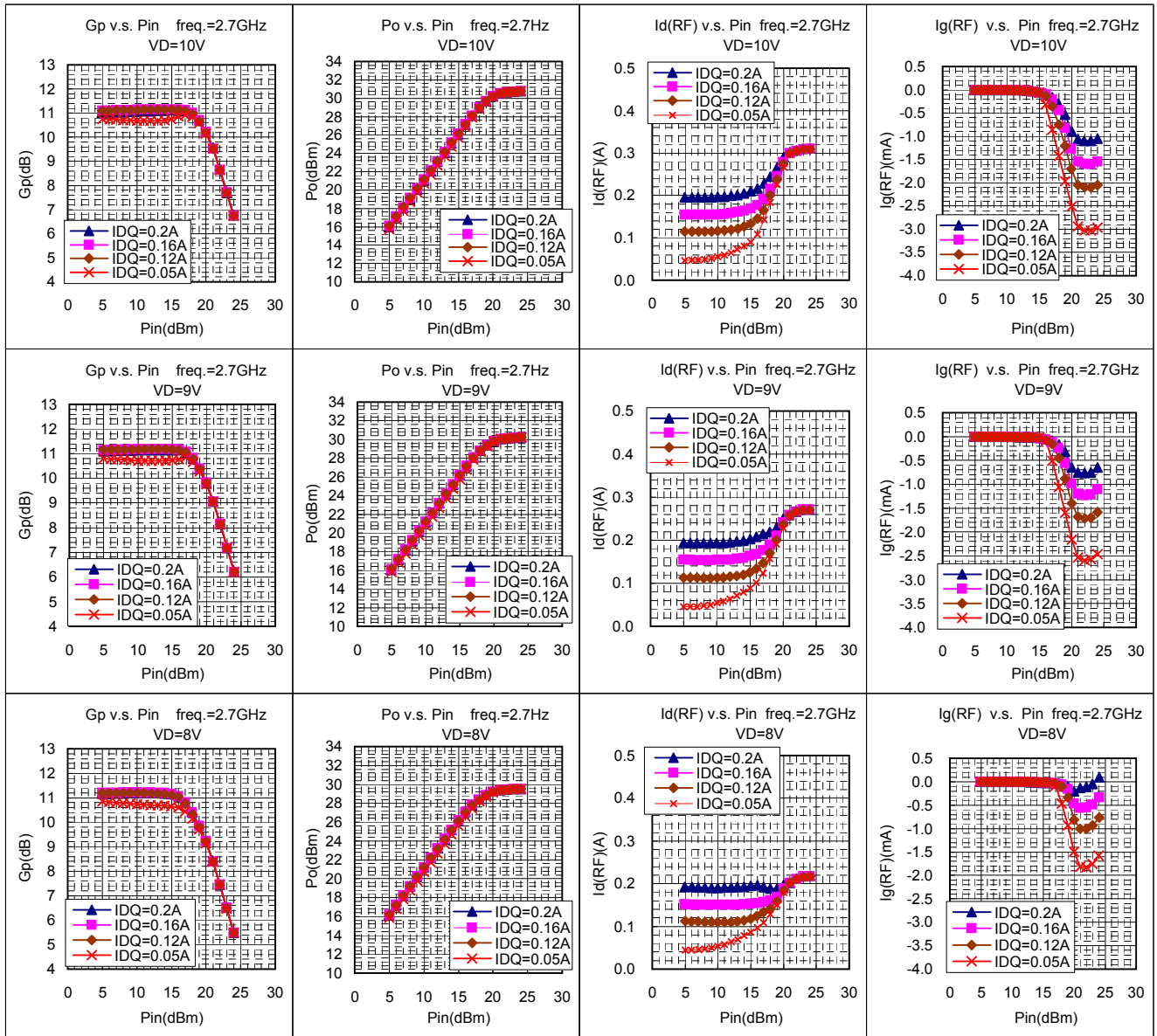
MGF0951P RF TEST DATA(CW)

Gp,Po,Id(RF),Ig(RF) v.s. Pin



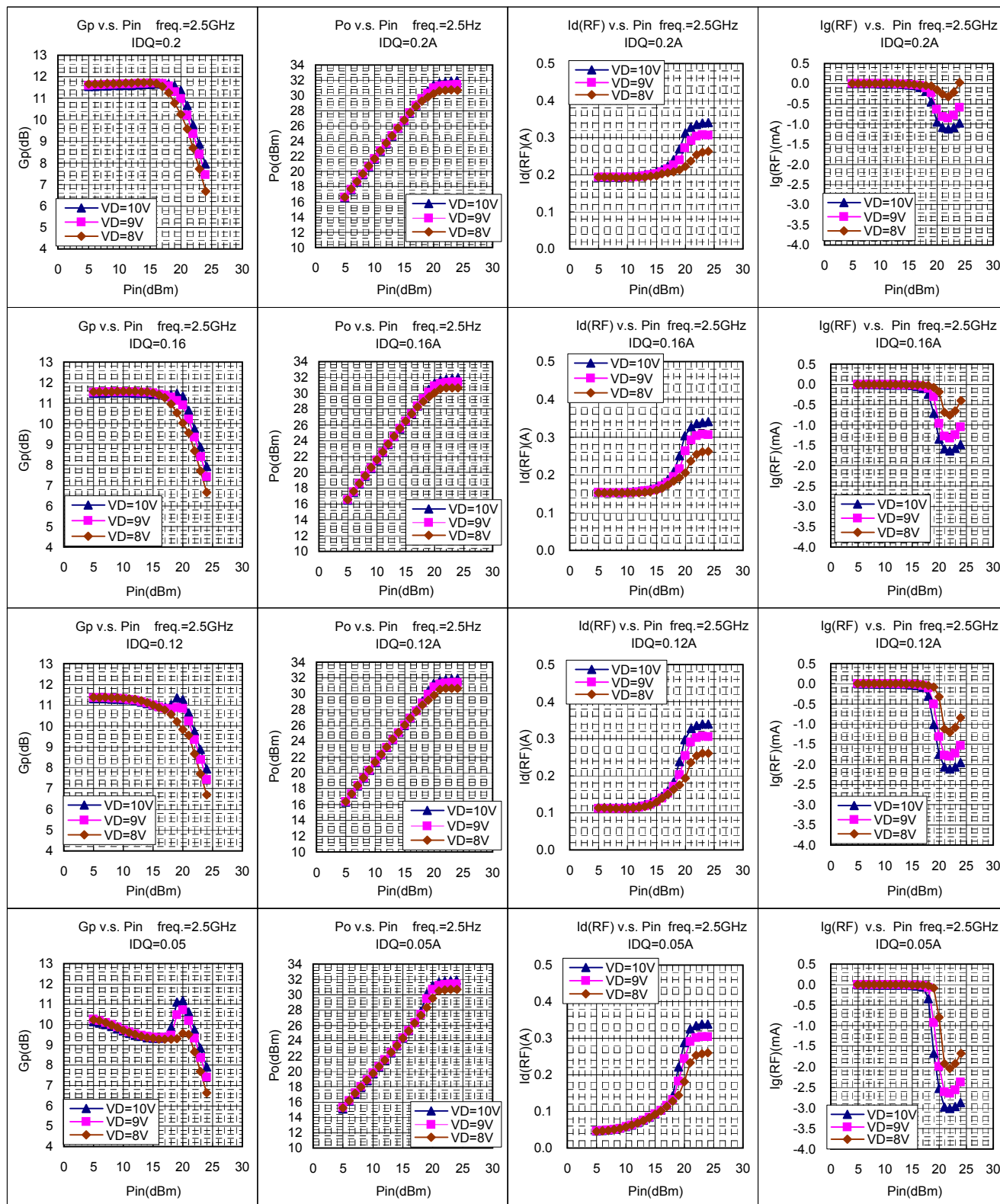
MGF0951P RF TEST DATA(CW)

Gp,Po,Id(RF),Ig(RF) v.s. Pin



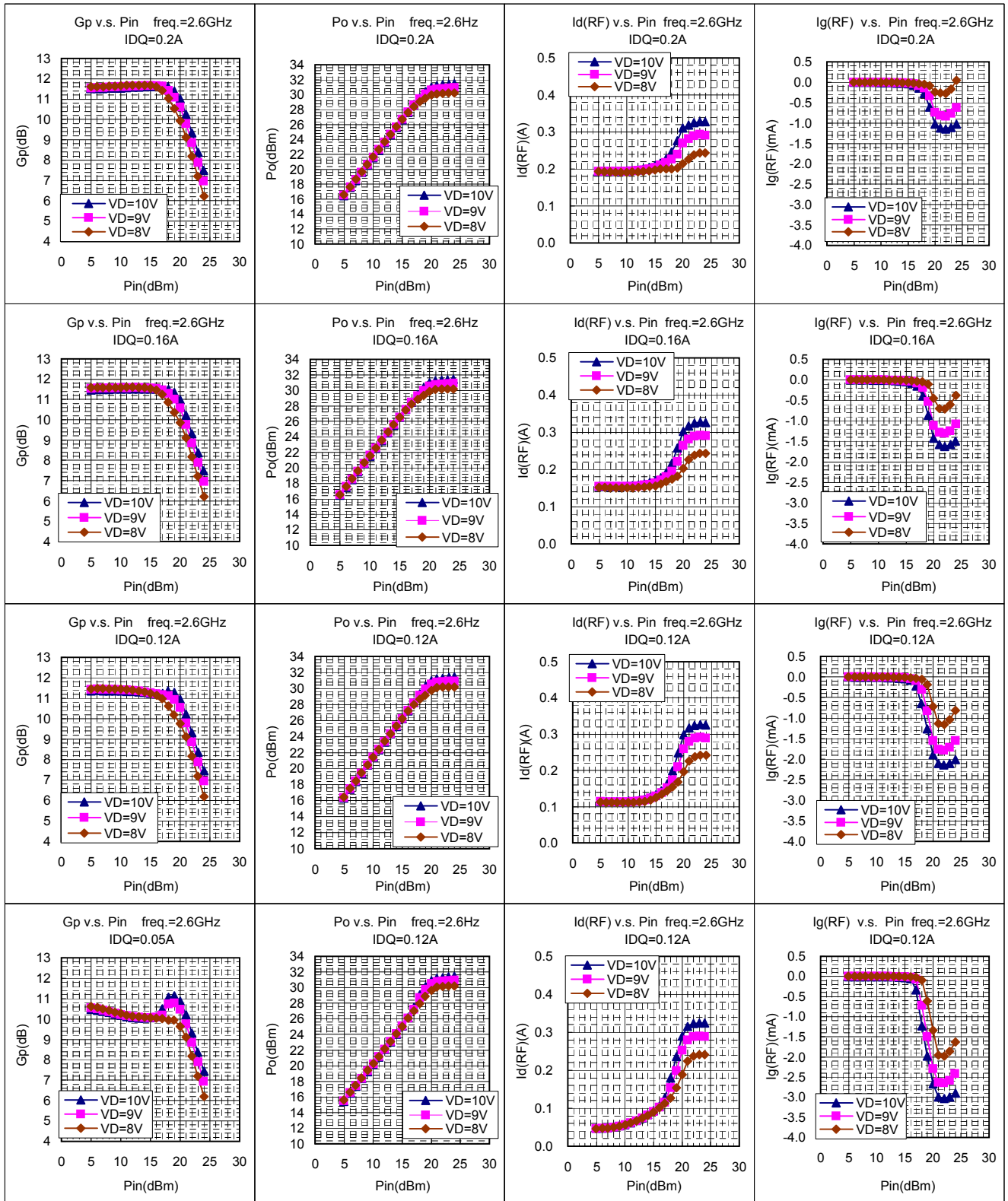
MGF0951P RF TEST DATA(CW)

Gp,Po,Id(RF),Ig(RF) v.s. Pin



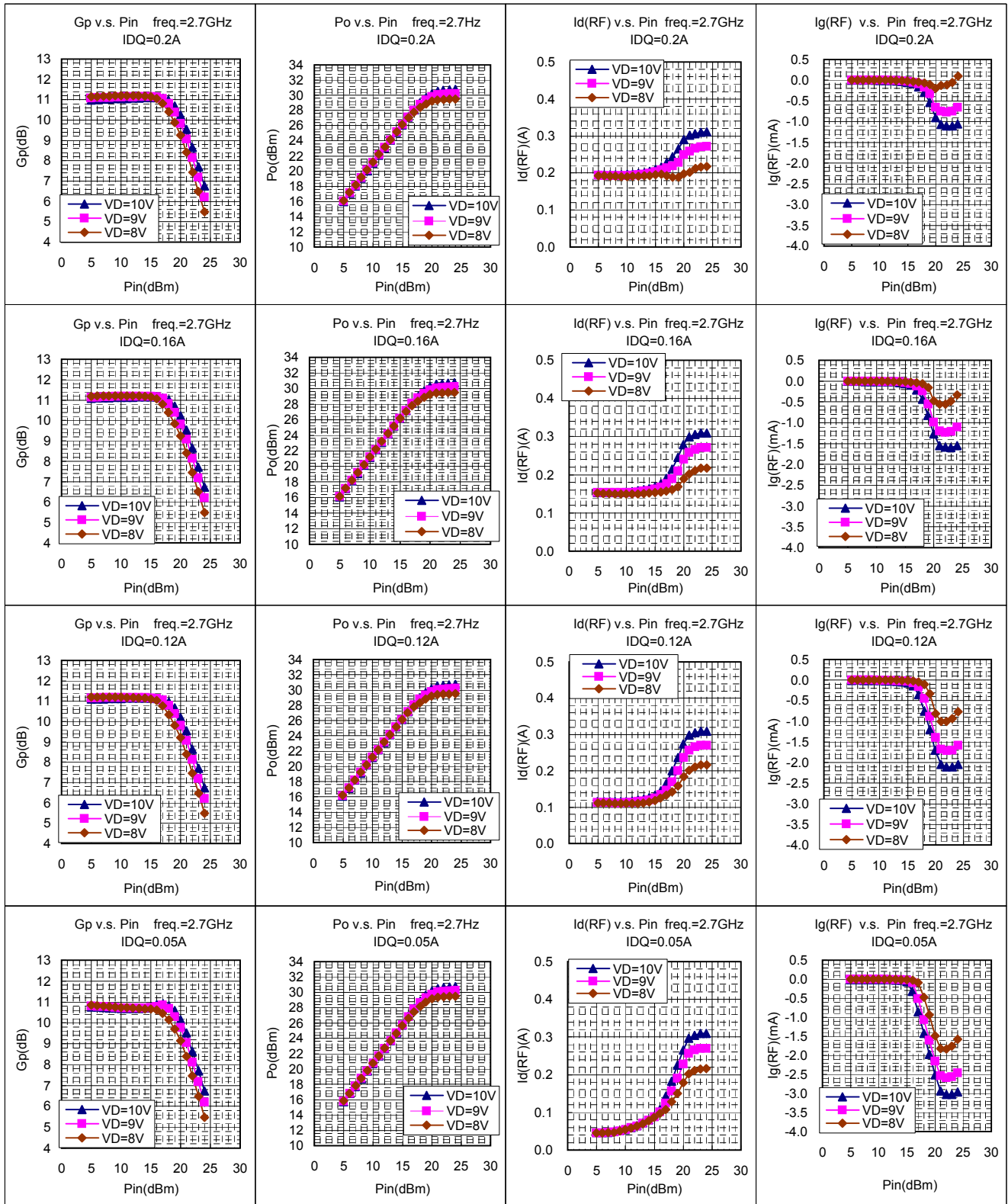
MGF0951P RF TEST DATA(CW)

Gp,Po,Id(RF),Ig(RF) v.s. Pin

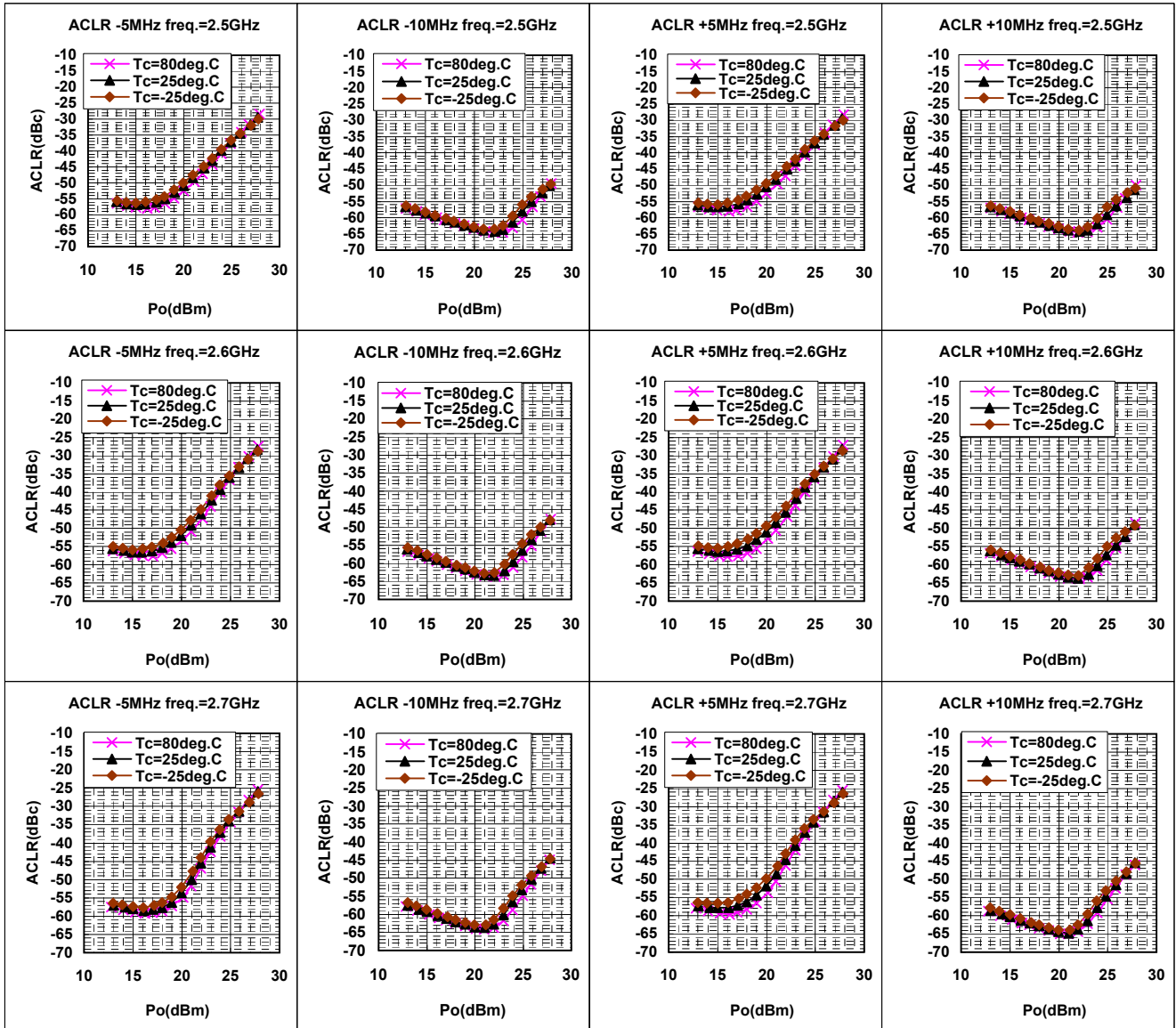


MGF0951P RF TEST DATA(CW)

Gp,Po,Id(RF),Ig(RF) v.s. Pin

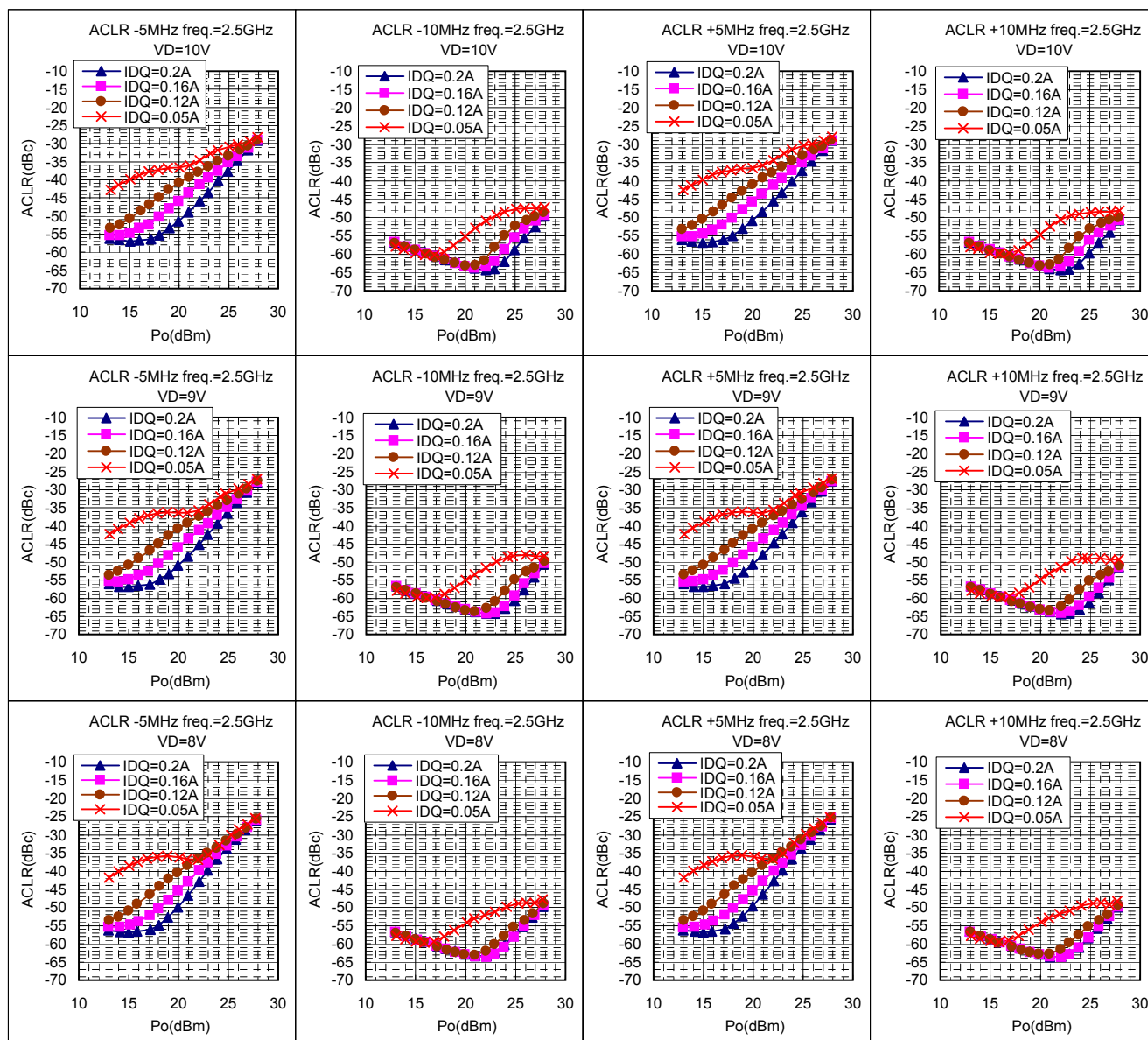


MGF0951P RF TEST DATA(W-CDMA) VD=10V,Idq=0.2A
ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal



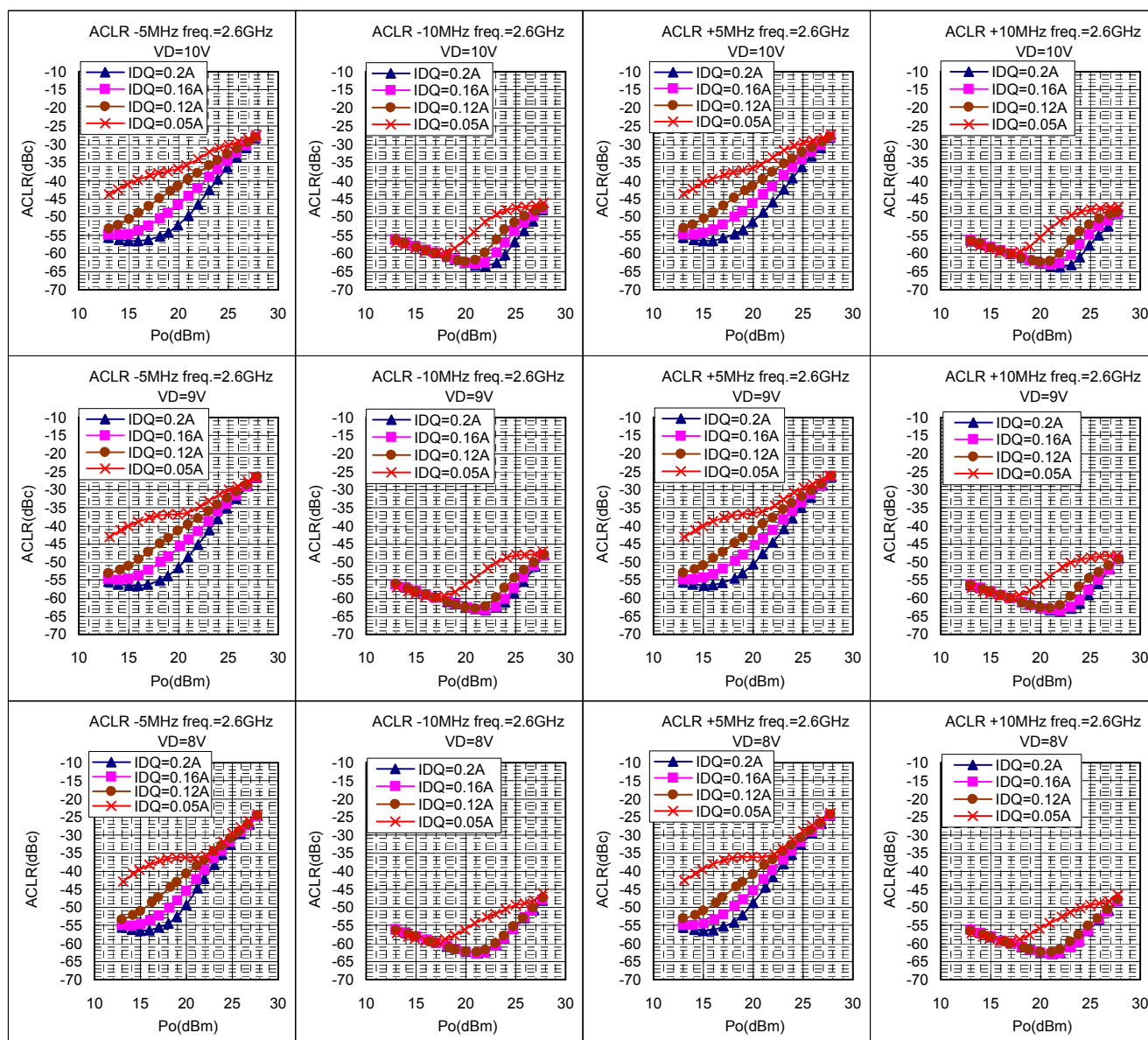
MGF0951P RF TEST DATA(W-CDMA)

ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal



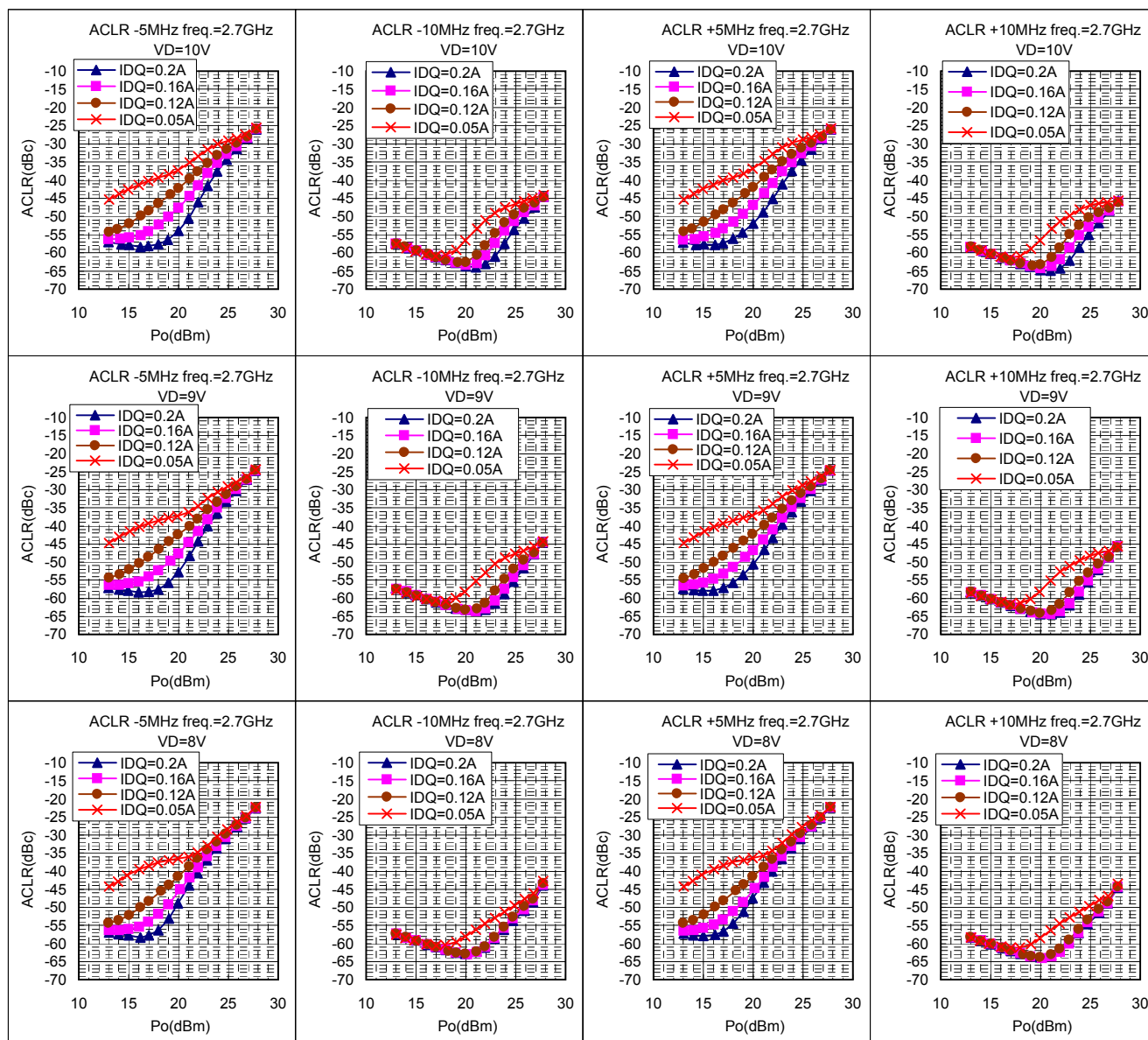
MGF0951P RF TEST DATA(W-CDMA)

ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal



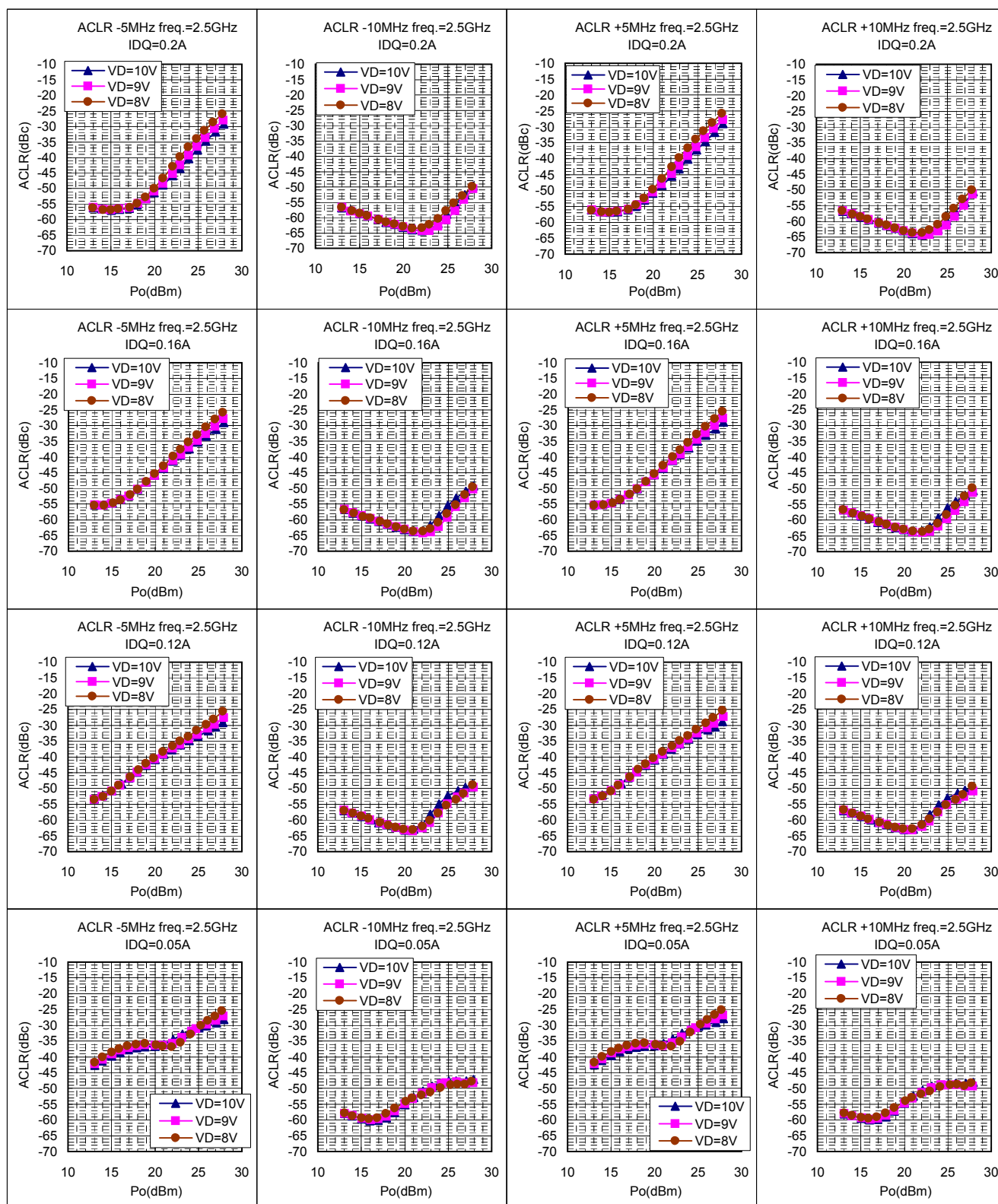
MGF0951P RF TEST DATA(W-CDMA)

ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal



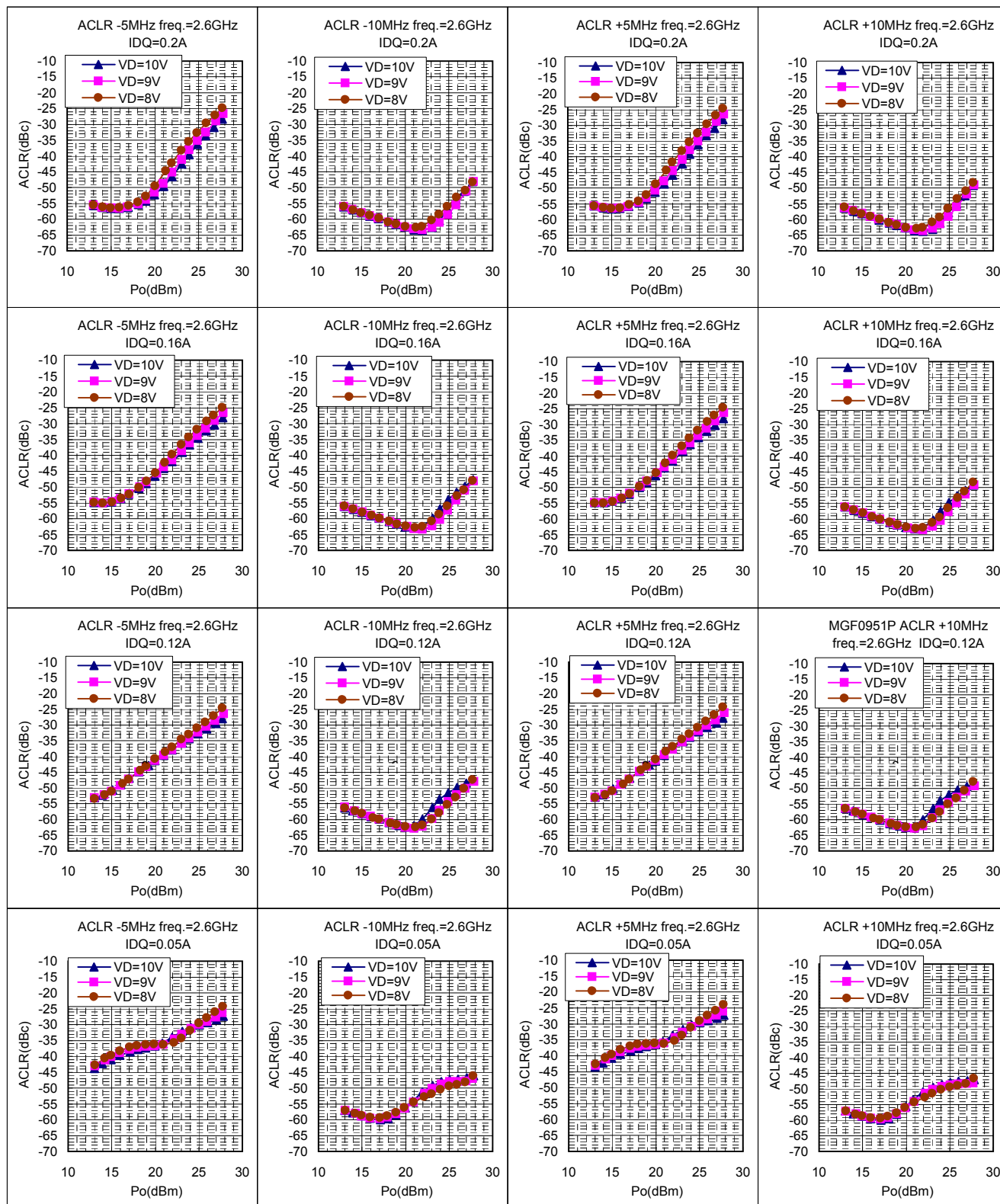
MGF0951P RF TEST DATA(W-CDMA)

ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal



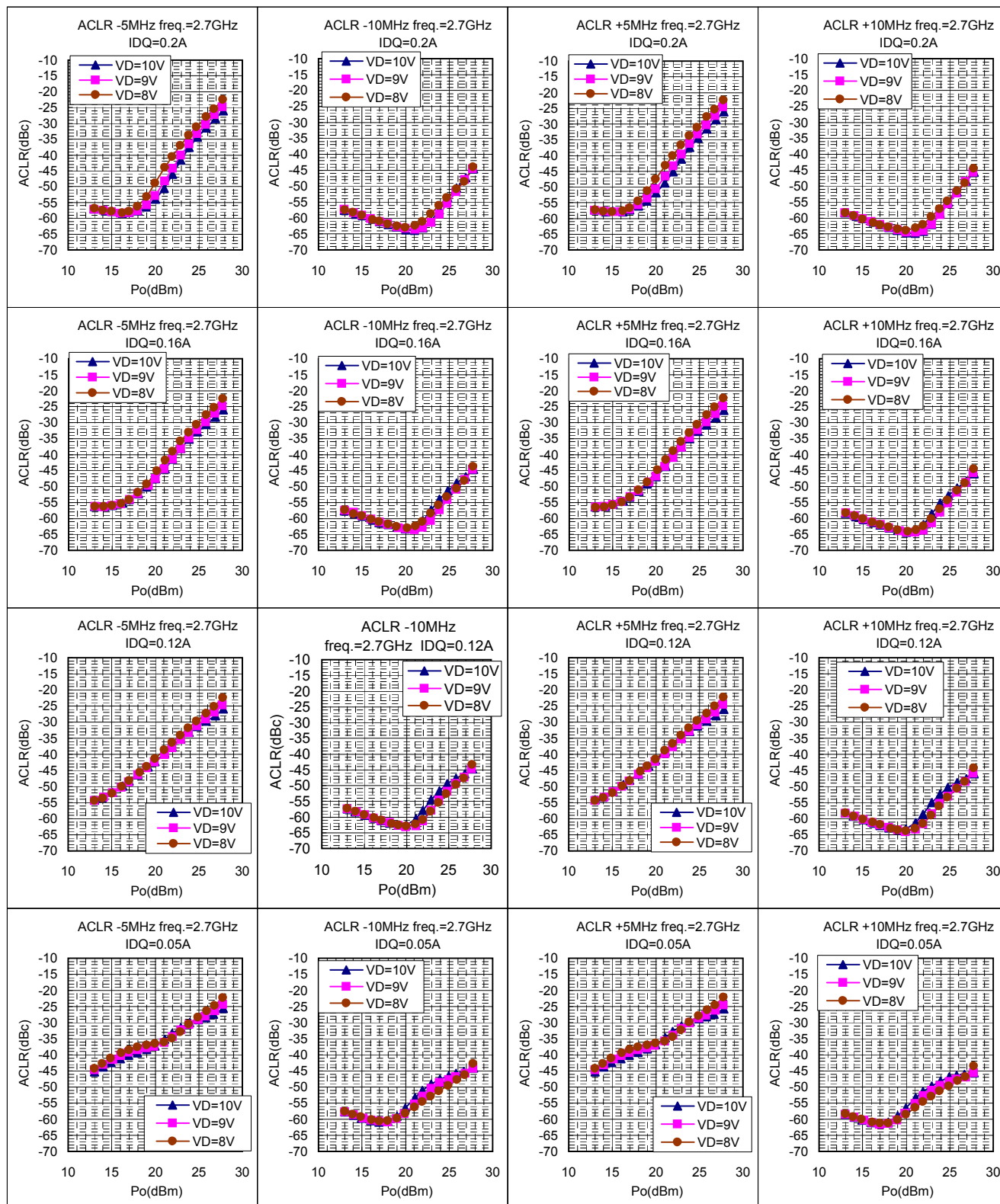
MGF0951P RF TEST DATA(W-CDMA)

ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal

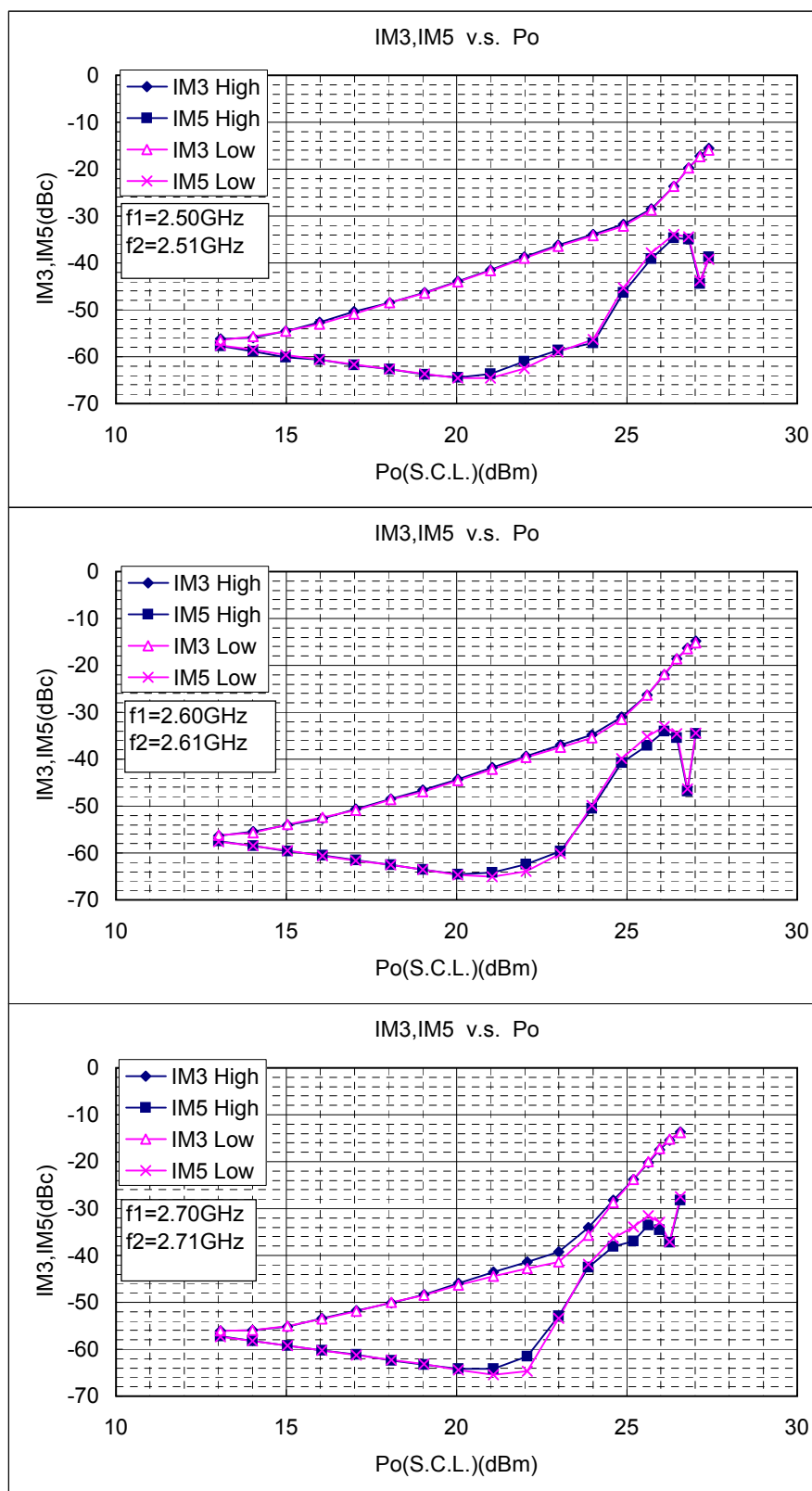


MGF0951P RF TEST DATA(W-CDMA)

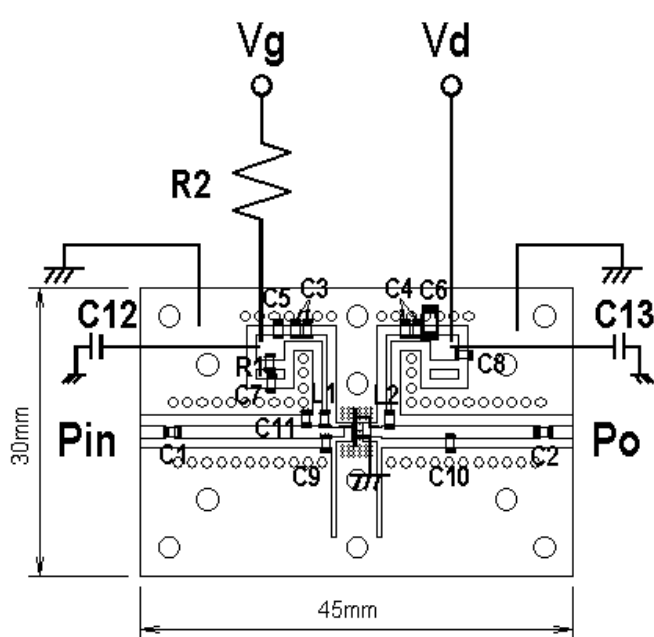
ACLR v.s. Po 3GPP TEST MODEL1 64ch's Single Signal



MGF0951P RF TEST DATA VD=10V, Idq=0.2A
IM3,IM5 v.s. Pin



MGF0951P TEST FIXTURE $f=2.6\text{GHz}$



C1,C2,C3,C4=20pF

C5,C7,C8=1000pF

C9=2pF

C10=1pF

C12,C13=47uF

C11=0.5pF

C6=4.7uF

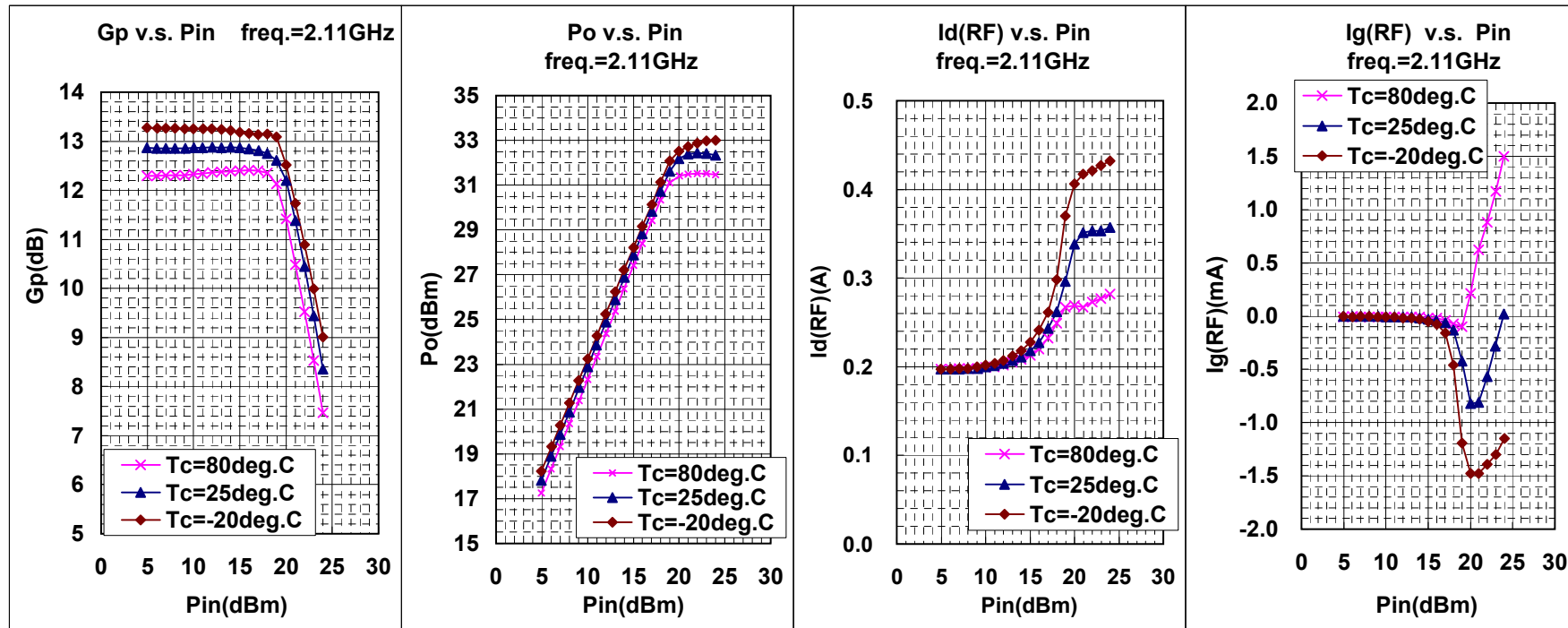
L1,L2=12nH

R1=51ohm

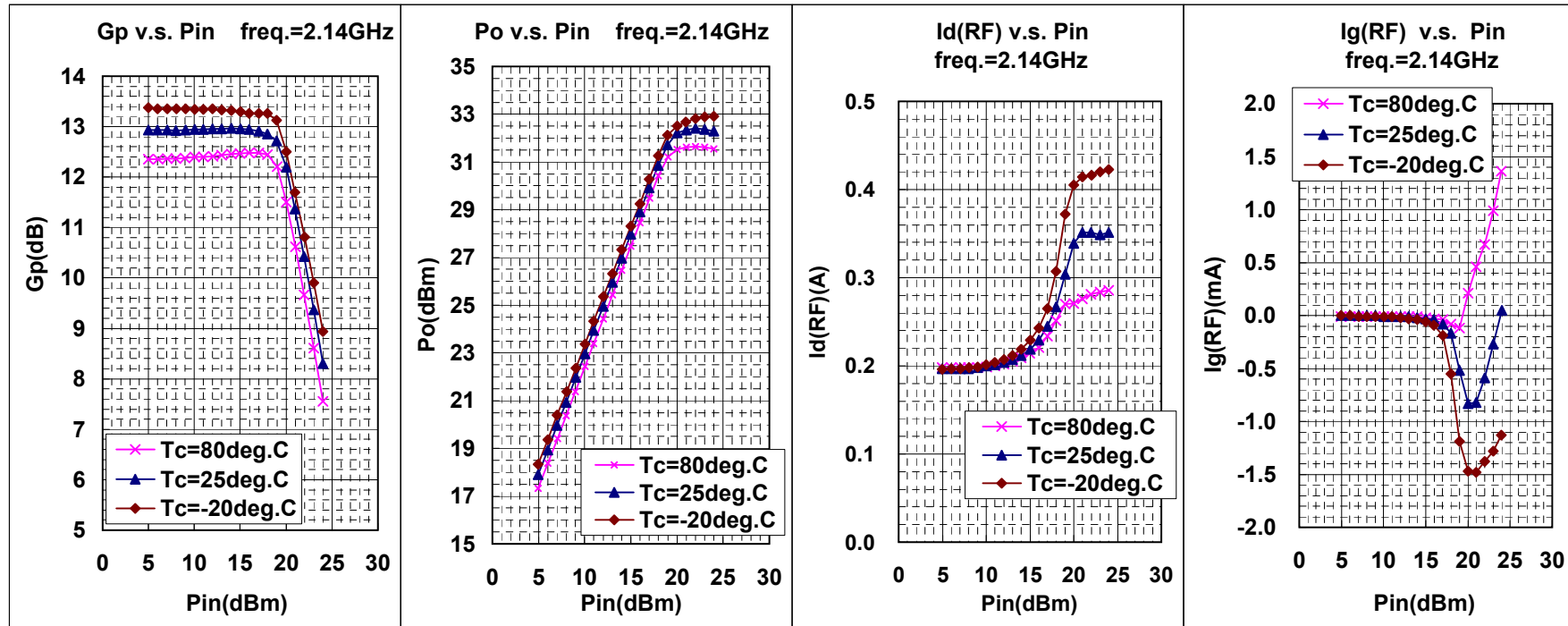
R2=500ohm

Board material:FR4 Thickness=0.8(mm)
Specific dielectric constant=4.4

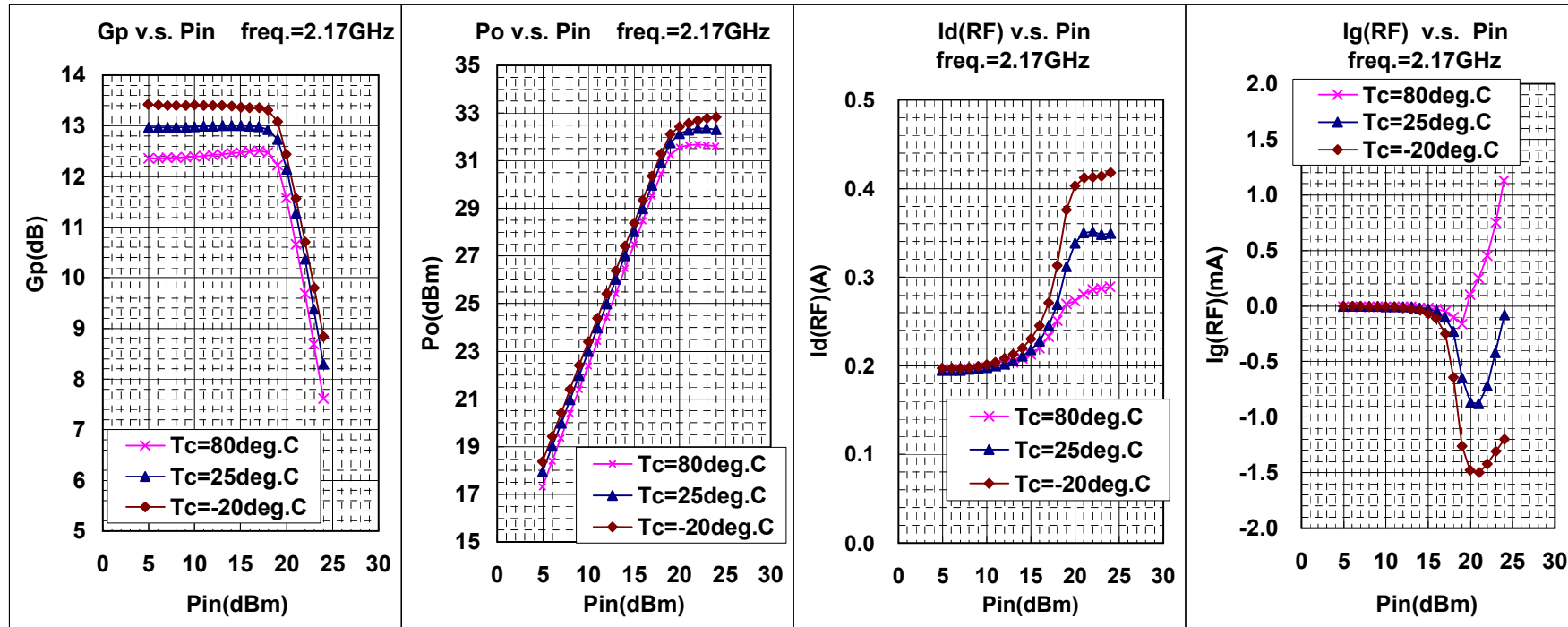
MGF0951P RF TEST DATA(CW) VD=10V,IDQ=0.2A
Gp,Po,Id(RF),Ig(RF) v.s. Pin



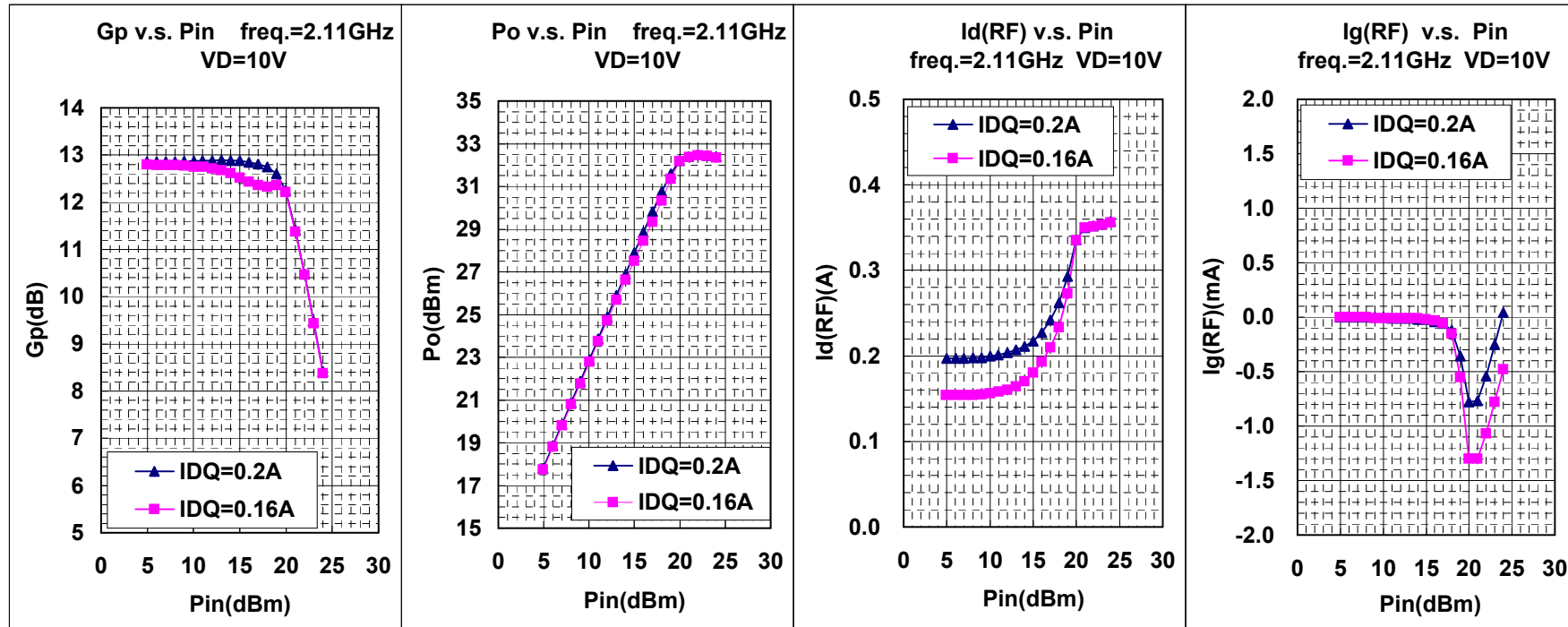
MGF0951P RF TEST DATA(CW) VD=10V,IDQ=0.2A
Gp,Po,Id(RF),Ig(RF) v.s. Pin



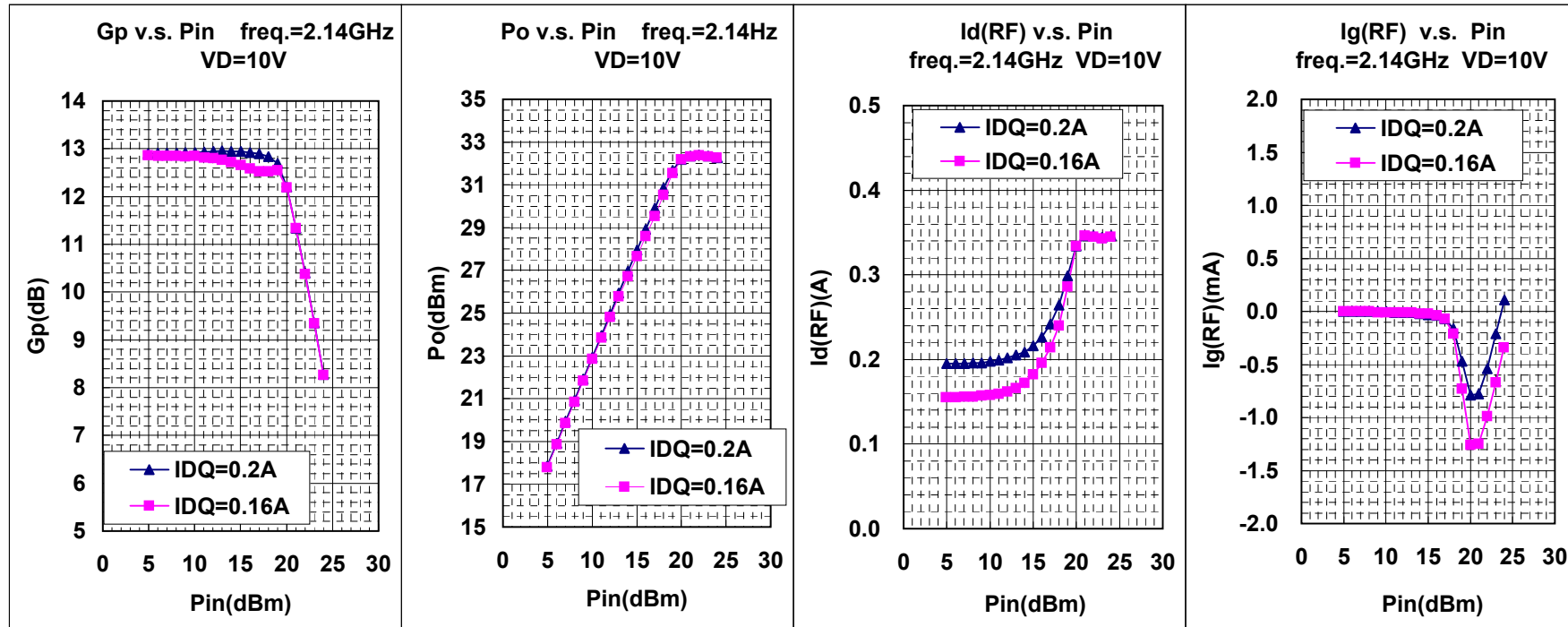
MGF0951P RF TEST DATA(CW) VD=10V, IDQ=0.2A
Gp, Po, Id(RF), Ig(RF) v.s. Pin



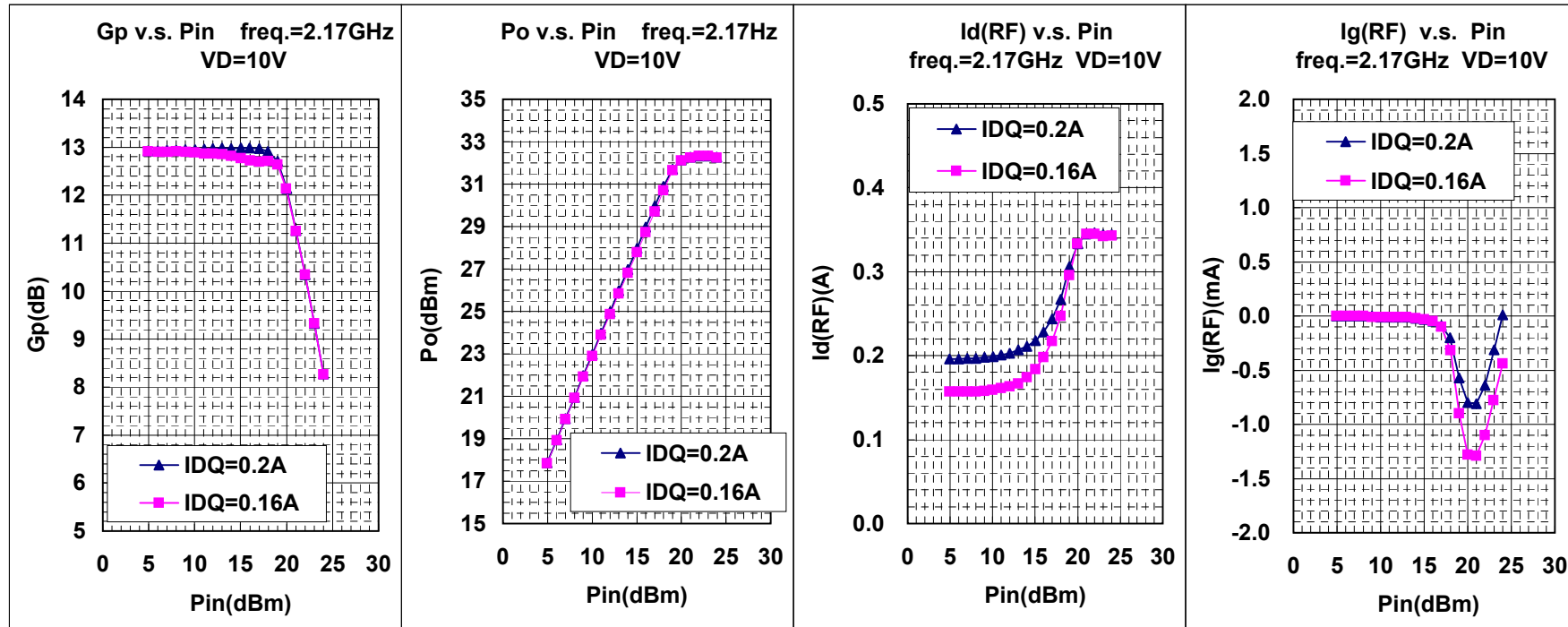
MGF0951P RF TEST DATA(CW)
Gp,Po,Id(RF),Ig(RF) v.s. Pin



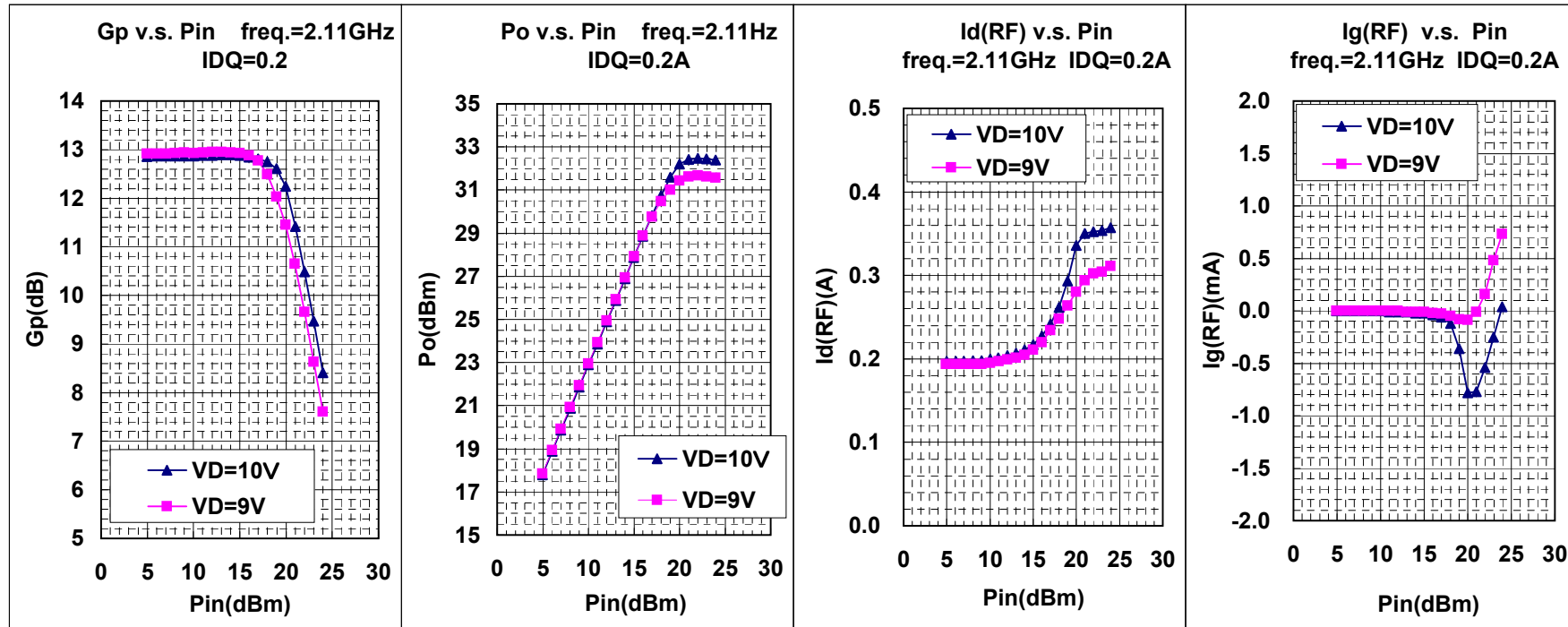
MGF0951P RF TEST DATA(CW)
Gp,Po,Id(RF),Ig(RF) v.s. Pin



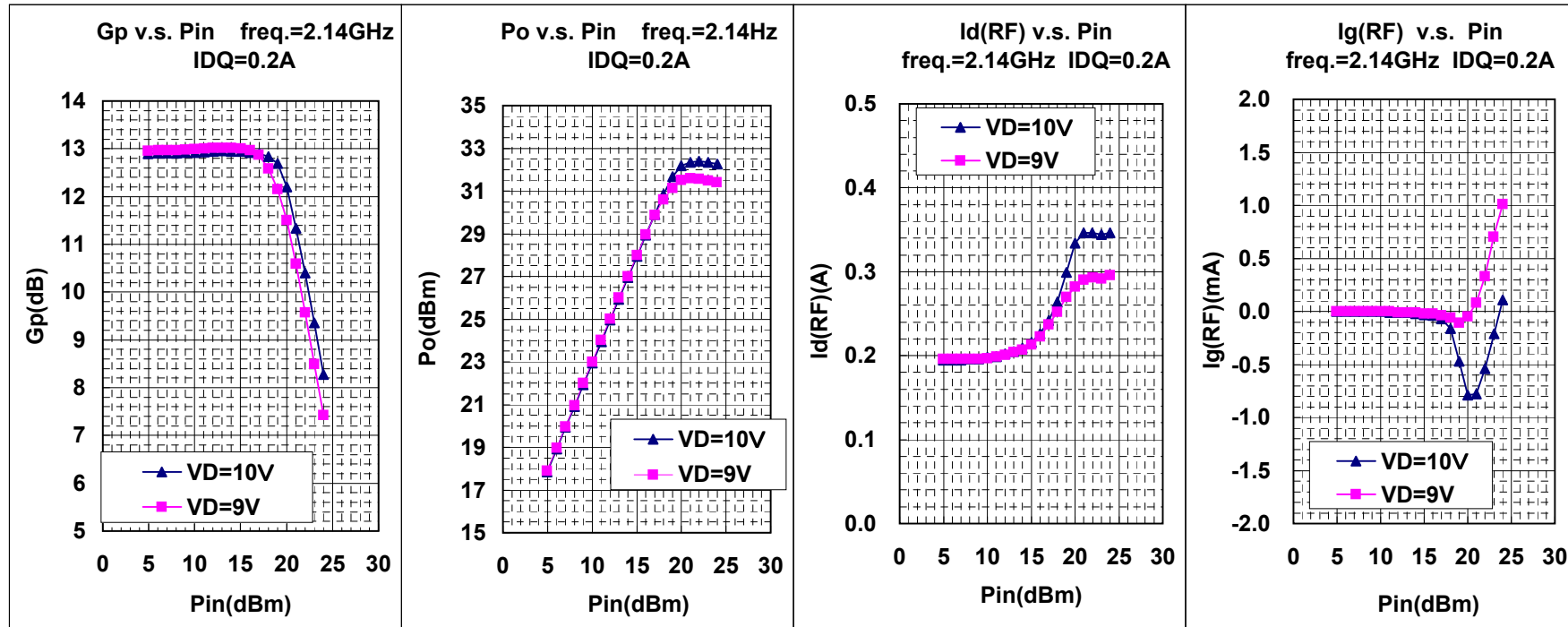
MGF0951P RF TEST DATA(CW)
Gp,Po,Id(RF),Ig(RF) v.s. Pin



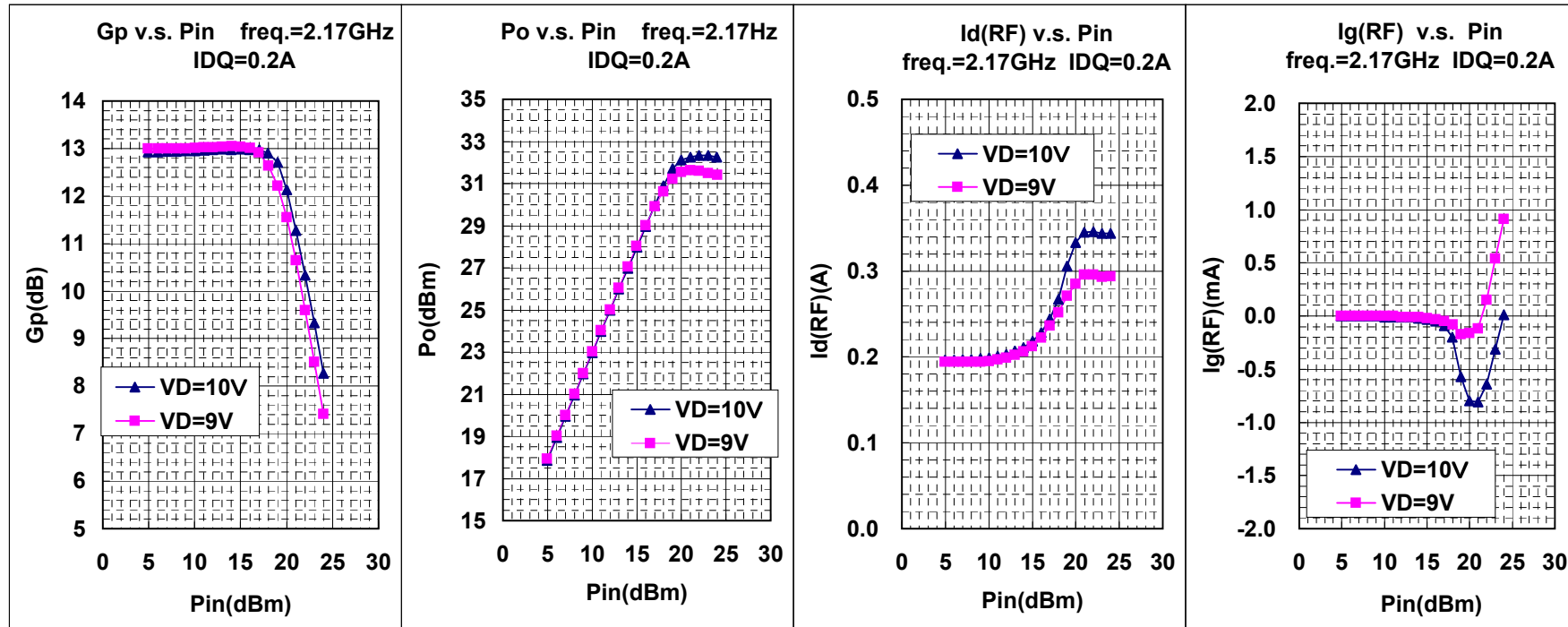
MGF0951P RF TEST DATA(CW)
Gp,Po,Id(RF),Ig(RF) v.s. Pin



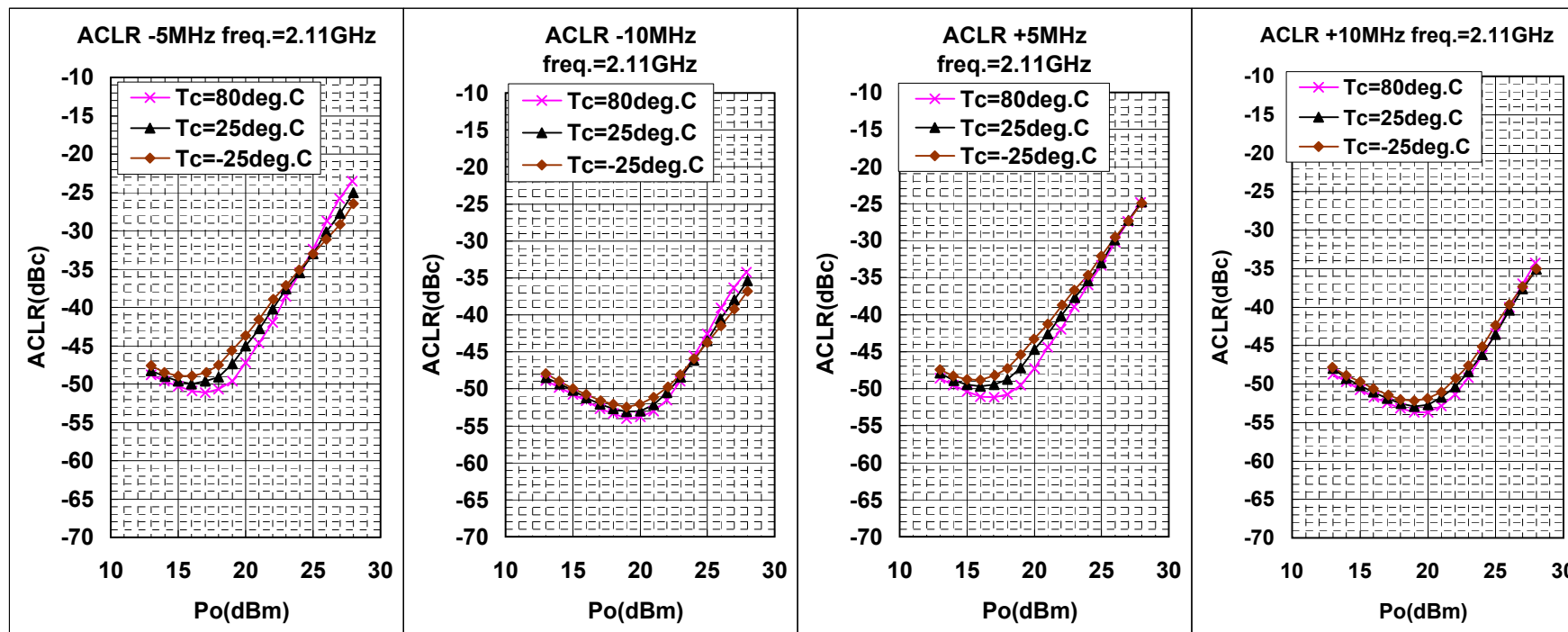
MGF0951P RF TEST DATA(CW)
Gp,Po,Id(RF),Ig(RF) v.s. Pin



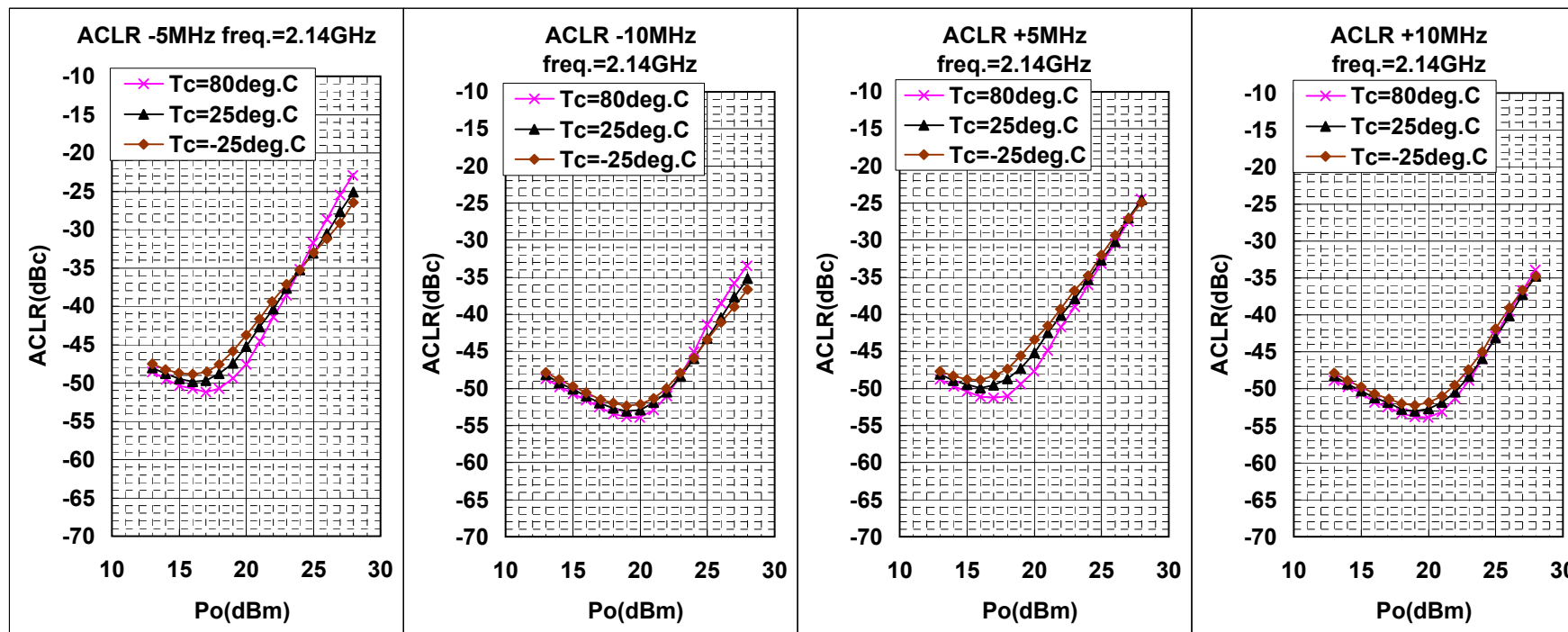
MGF0951P RF TEST DATA(CW)
Gp,Po,Id(RF),Ig(RF) v.s. Pin



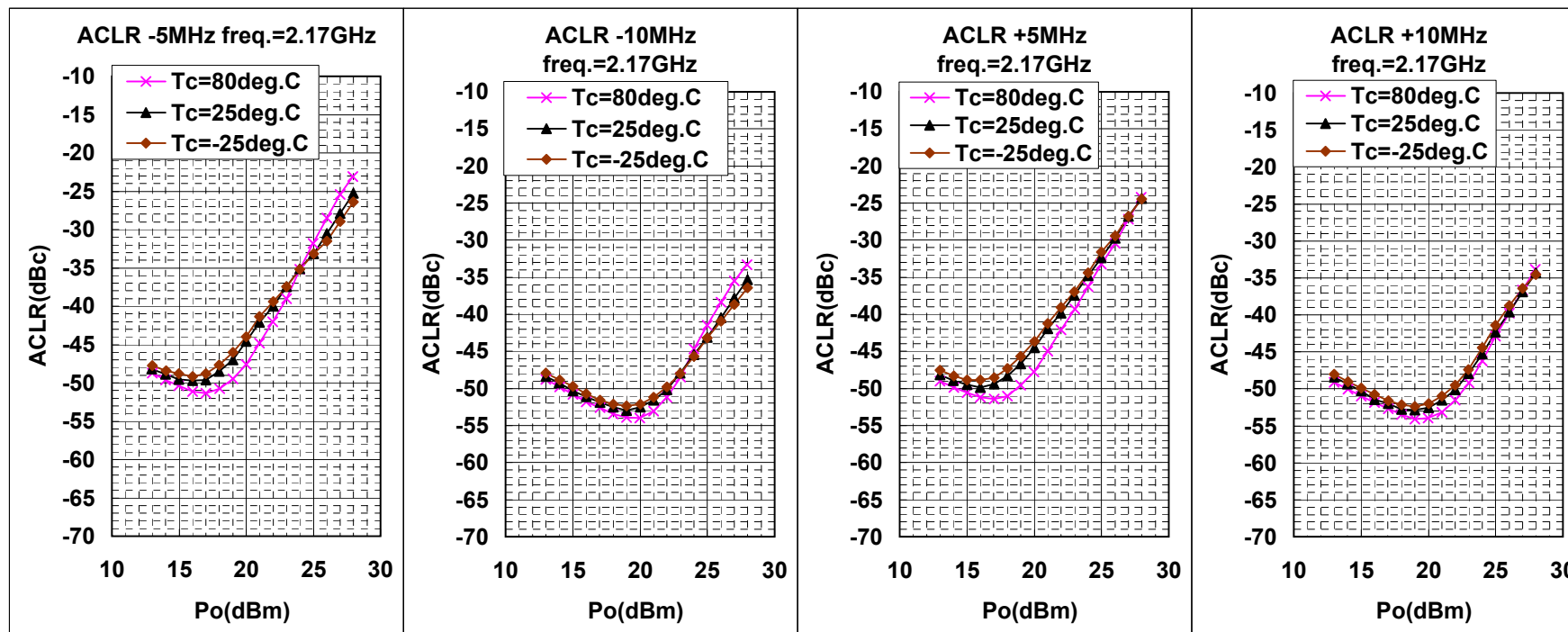
MGF0951P RF TEST DATA(W-CDMA) VD=10V,IDQ=0.2A
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



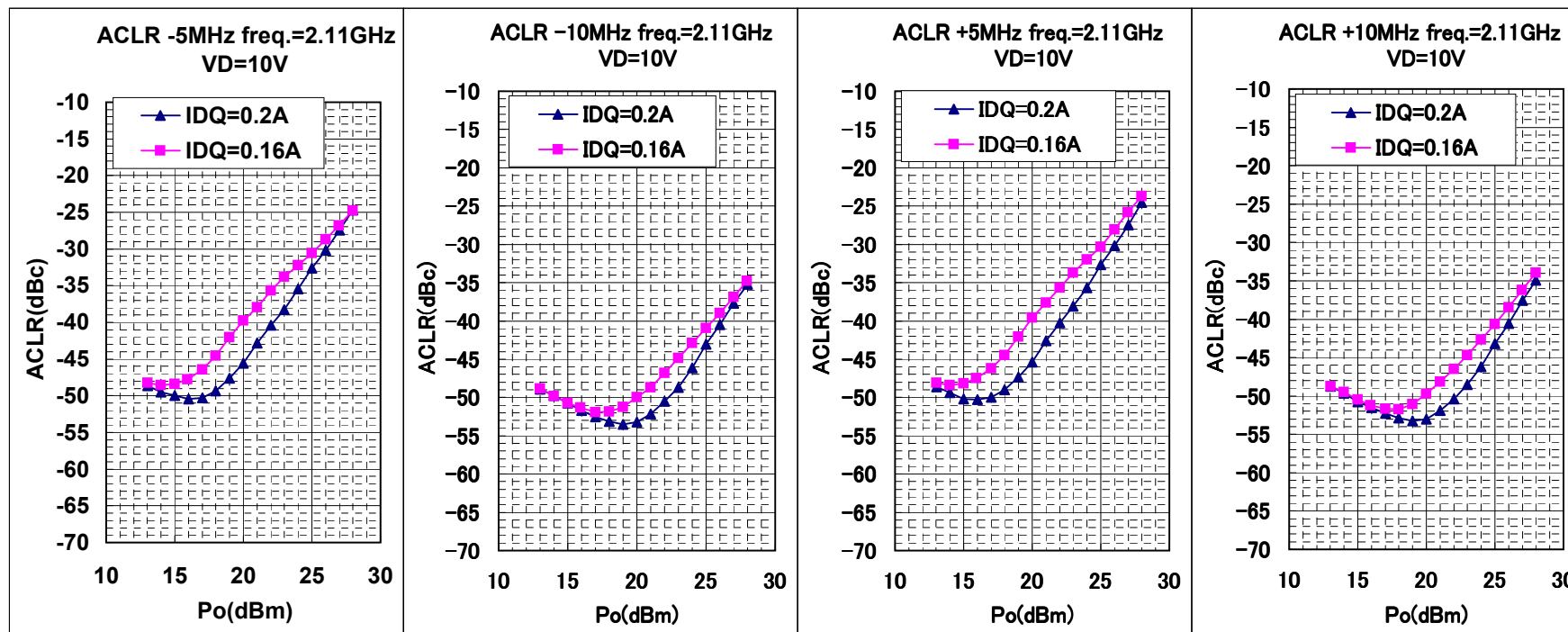
MGF0951P RF TEST DATA(W-CDMA) VD=10V,IDQ=0.2A
 ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



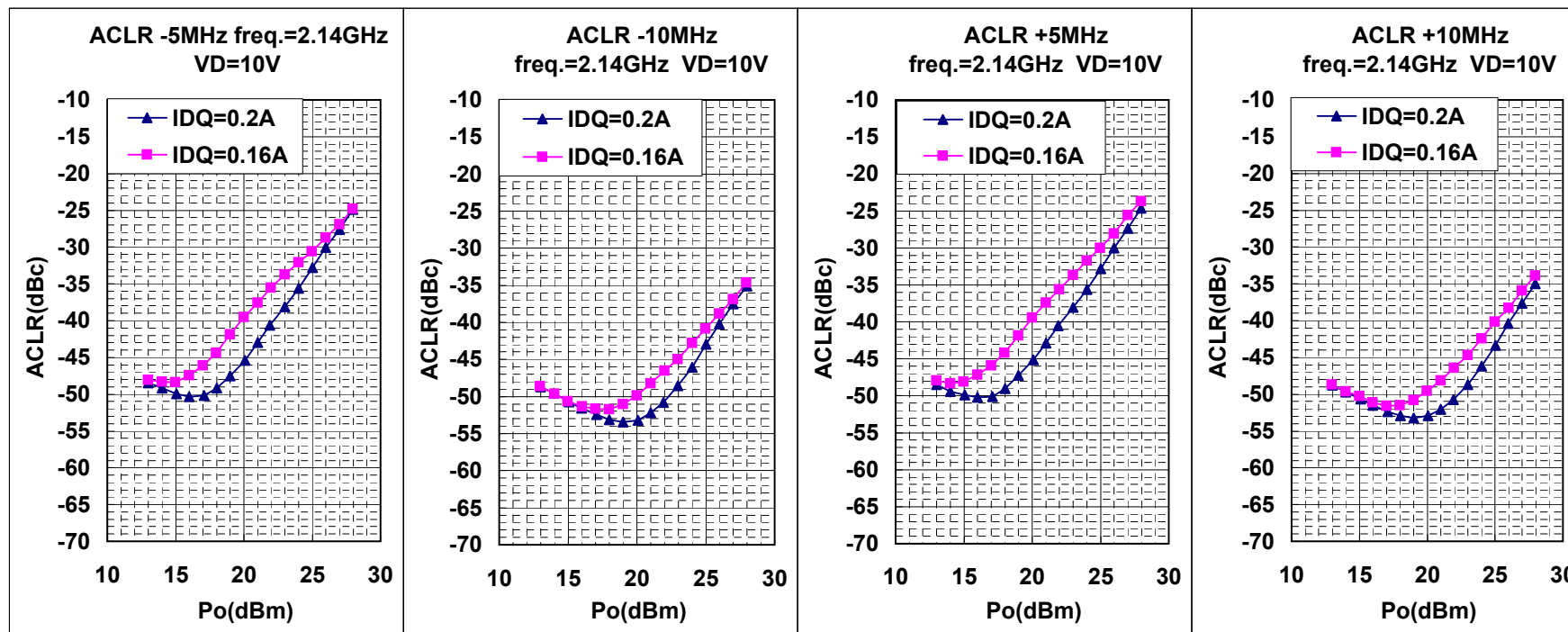
MGF0951P RF TEST DATA(W-CDMA) VD=10V,IDQ=0.2A
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



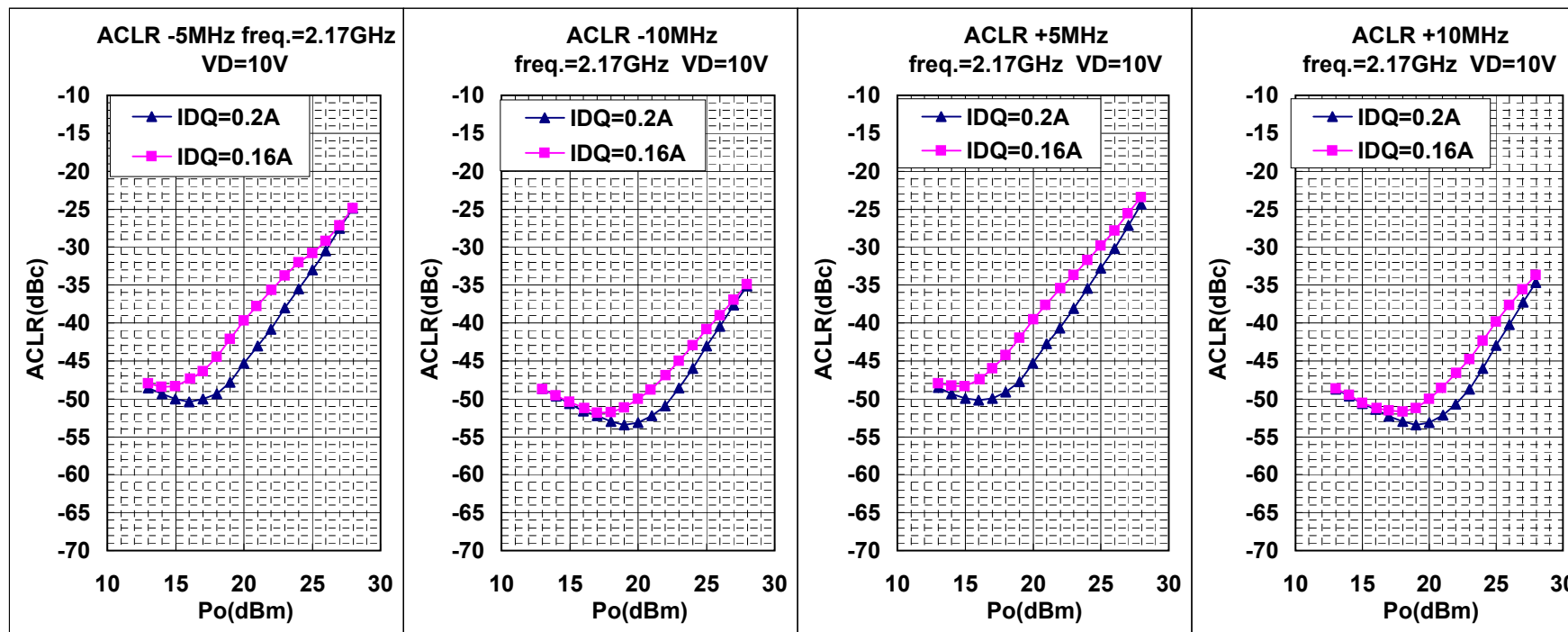
MGF0951P RF TEST DATA(W-CDMA)
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



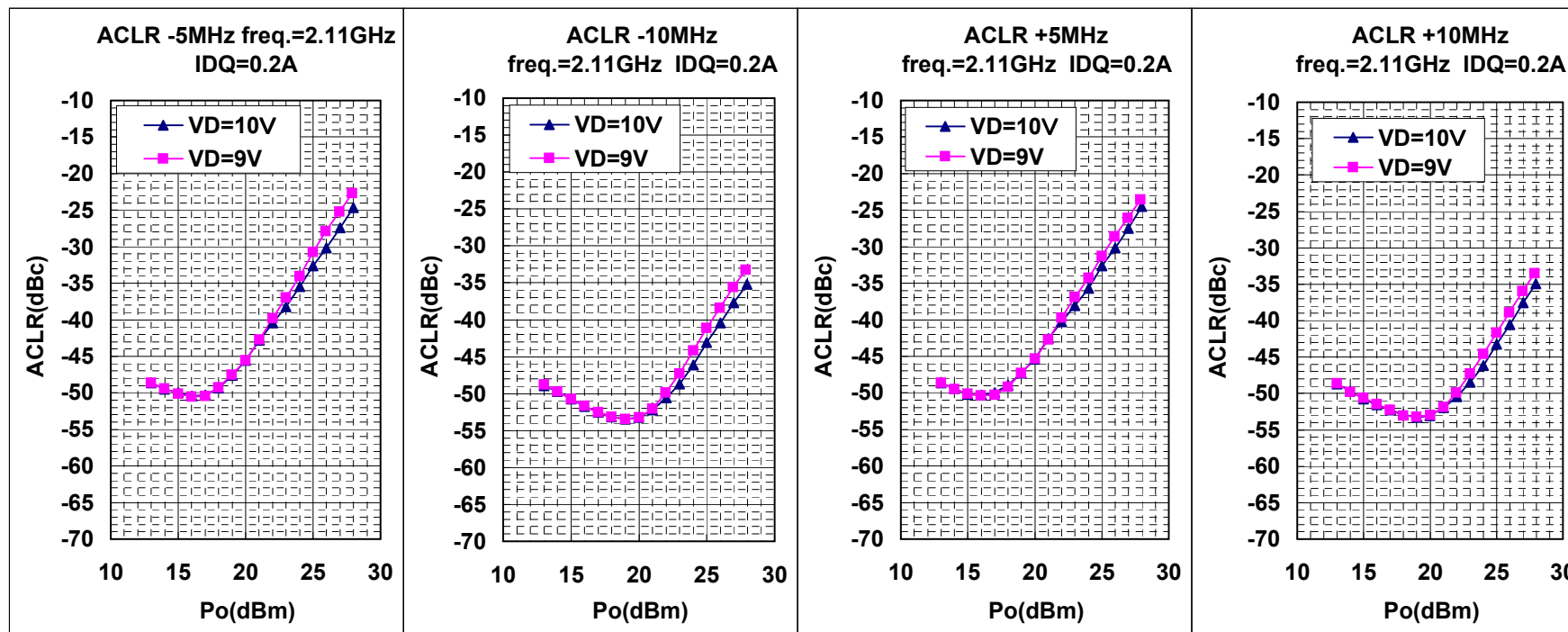
MGF0951P RF TEST DATA(W-CDMA)
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



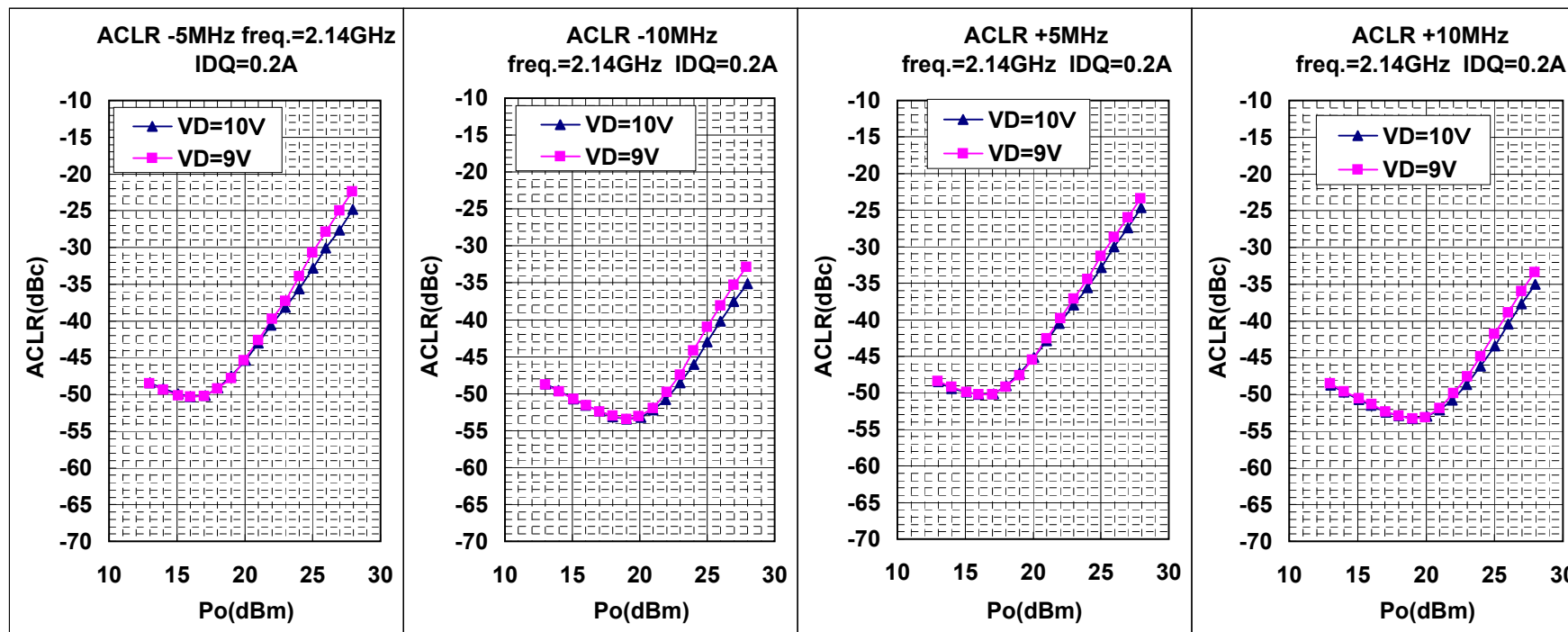
MGF0951P RF TEST DATA(W-CDMA)
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



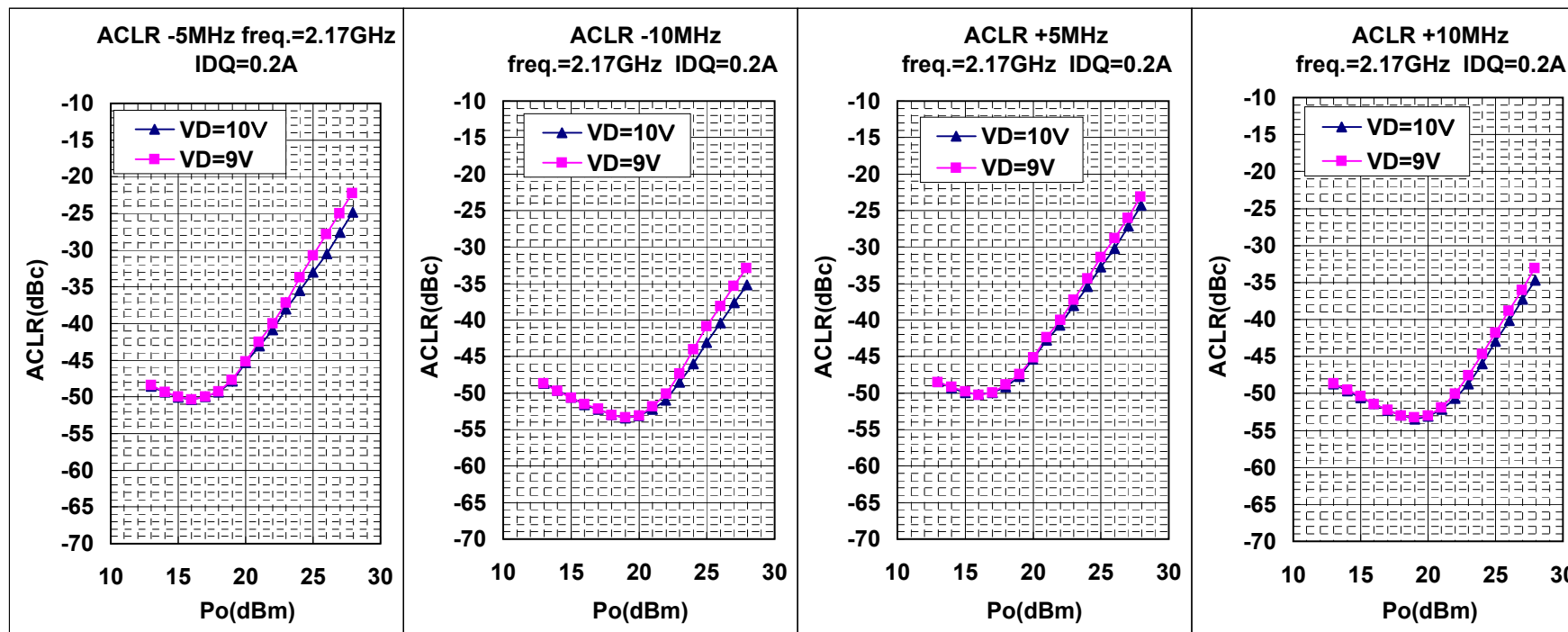
MGF0951P RF TEST DATA(W-CDMA)
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



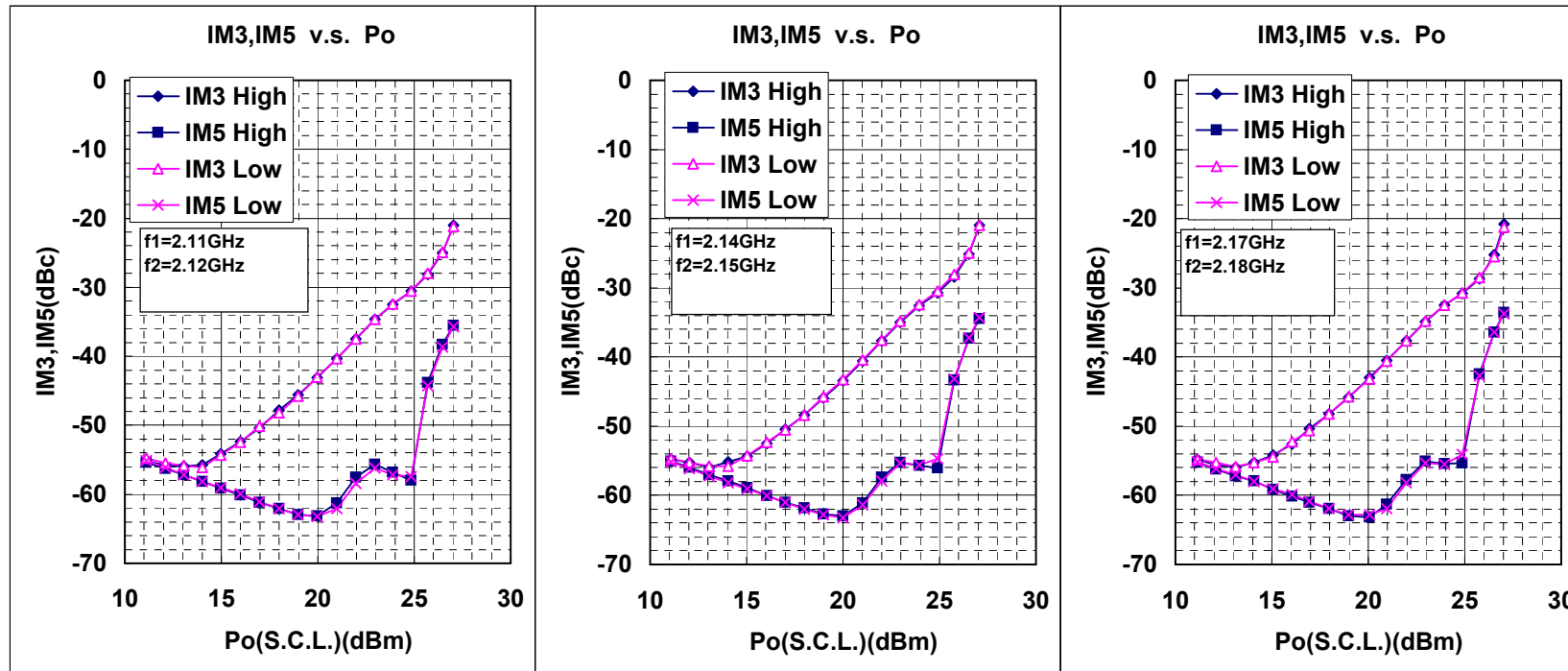
MGF0951P RF TEST DATA(W-CDMA)
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



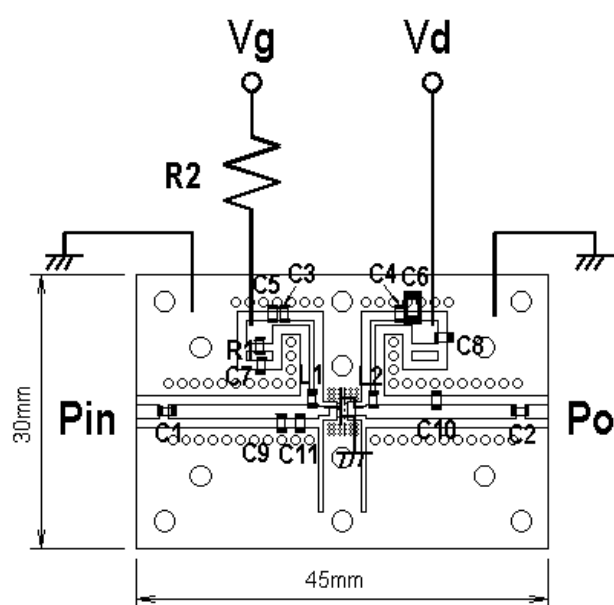
MGF0951P RF TEST DATA(W-CDMA)
ACLR v.s. Po 3GPP TEST MODEL1 64ch's 2carrier Signal



MGF0951P RF TEST DATA VD=10V, IDQ=0.2A
IM3, IM5 v.s. Pin



MGF0951P TEST FIXTURE $f=2.11\text{-}2.17\text{GHz}$



C1,C2,C3,C4=20pF

C5,C7,C8=1000pF

C9=2pF

C10=1pF

C11=0.5pF

C6=4.7uF

L1,L2=12nH

R1=51ohm

R2=500ohm

Board material:FR4 Thickness=0.8(mm)

Specific dielectric constant=4.4

L & S BAND GaAs FET [Plastic Mold Lead-less PKG]**Requests Regarding Safety Designs**

Mitsubishi Electric constantly strives to raise the level of its quality and reliability. Despite these concerted efforts, however, there will be occasions when our semiconductor products suffer breakdowns, malfunctions or other problems. In view of this reality, it is requested that every feasible precaution be taken in the pursuit of redundancy design, malfunction prevention design and other safety-related designs, to prevent breakdowns or malfunctions in our products from resulting in accidents involving people, fires, social losses or other problems, thereby upholding the highest levels of safety in the products when in use by customers.

Matters of Importance when Using these Materials

1. These materials are designed as reference materials to ensure that all customers purchase Mitsubishi Electric semiconductors best suited to their specific use applications. Please be aware, however, that the technical information contained in these materials does not comprise consent for the execution or use of intellectual property rights or other rights owned by Mitsubishi Electric Corporation.
2. Mitsubishi Electric does not assume responsibility for damages resulting from the use of product data, graphs, charts, programs, algorithms or other applied circuit examples described in these materials, or for the infringement of the rights of third-party owners resulting from such use.
3. The data, graphs, charts, programs, algorithms and all other information described in these materials were current at the issue of these materials, with Mitsubishi Electric reserving the right to make any necessary updates or changes in the products or specifications in these materials without prior notice. Before purchasing Mitsubishi Electric semiconductor products, therefore, please obtain the latest available information from Mitsubishi Electric directly or an authorized dealer.
4. Every possible effort has been made to ensure that the information described in these materials is fully accurate. However, Mitsubishi Electric assumes no responsibility for damages resulting from inaccuracies occurring within these materials.
5. When using the product data, technical contents indicated on the graphs, charts, programs or algorithms described in these materials, assessments should not be limited to only the technical contents, programs and algorithm units. Rather, it is requested that ample evaluations be made of each individual system as a whole, with the customer assuming full responsibility for decisions on the propriety of application. Mitsubishi Electric does not accept responsibility for the propriety of application.
6. The products described in these materials, with the exception of special mention concerning use and reliability, have been designed and manufactured with the purpose of use in general electronic machinery. Accordingly these products have not been designed and manufactured with the purpose of application in machinery or systems that will be used under conditions that can affect human life, or in machinery or systems used in social infrastructure that demand a particularly high degree of reliability. When considering the use of the products described in these materials in transportation machinery (automobiles, trains, vessels), for objectives related to medical treatment, aerospace, nuclear power control, submarine repeaters or systems or other specialized applications, please consult with Mitsubishi Electric directly or an authorized dealer.
7. When considering use of products for purposes other than the specific applications described in these materials, please inquire at Mitsubishi Electric or an authorized dealer.
8. The prior consent of Mitsubishi Electric in writing is required for any reprinting or reproduction of these materials.
9. Please direct any inquiries regarding further details of these materials, or any other comments or matters of attention, to Mitsubishi Electric or an authorized dealer.